



US005351255A

United States Patent [19]

[11] Patent Number: 5,351,255

Schetzina

[45] Date of Patent: Sep. 27, 1994

[54] **INVERTED INTEGRATED HETEROSTRUCTURE OF GROUP II-VI SEMICONDUCTOR MATERIALS INCLUDING EPITAXIAL OHMIC CONTACT AND METHOD OF FABRICATING SAME**

[75] Inventor: Jan F. Schetzina, Cary, N.C.

[73] Assignee: North Carolina State University of Raleigh, Raleigh, N.C.

[21] Appl. No.: 54,040

[22] Filed: Apr. 28, 1993

Related U.S. Application Data

[63] Continuation-in-part of Ser. No. 934,190, Aug. 21, 1992, Pat. No. 5,294,833, which is a continuation-in-part of Ser. No. 881,599, May 12, 1992.

[51] Int. Cl.⁵ H01S 3/19

[52] U.S. Cl. 372/45; 372/43; 257/12; 257/200; 257/201; 437/129

[58] Field of Search 372/45, 43; 257/12, 257/13, 200, 201; 437/129

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(List continued on next page.)

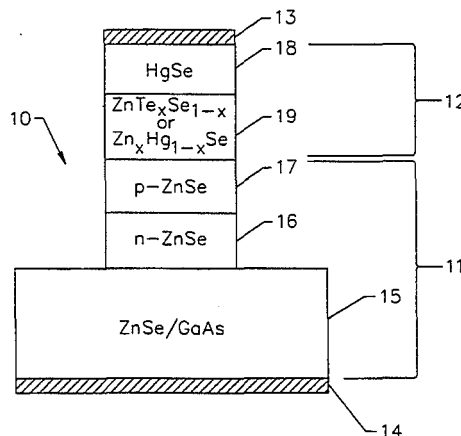
Primary Examiner—Georgia Y. Epps

Attorney, Agent, or Firm—Bell, Seltzer, Park & Gibson

[57] ABSTRACT

An inverted integrated heterostructure includes an optical emission heterostructure formed of Group II-VI compound semiconductor materials having first and second opposing faces and including a layer of p-type zinc selenide or an alloy thereof at the first face. A zinc mercury selenide or a zinc telluride selenide layer is formed on the layer of p-type zinc selenide or an alloy thereof, and a mercury selenide layer is formed on the zinc mercury selenide or zinc telluride selenide layer, opposite the optical emission heterostructure. An ohmic electrode is formed on the mercury selenide layer opposite the zinc mercury selenide or a zinc telluride selenide layer, and a transparent ohmic electrode is formed on the second face of the optical emission heterostructure for allowing optical emissions from the optical emission heterostructure to pass therethrough. The ohmic electrode is preferably an optically reflecting ohmic electrode for reflecting optical emissions from the optical emission heterostructure back into the optical emission heterostructure. A substrate is also preferably included on the ohmic electrode opposite the mercury selenide layer. The substrate is preferably an electrically and thermally conducting substrate. The integrated heterostructure may be formed by forming an optical emission heterostructure including an epitaxial ohmic contact on a first substrate, bonding the ohmic contact to a second substrate and then removing the first substrate.

26 Claims, 35 Drawing Sheets



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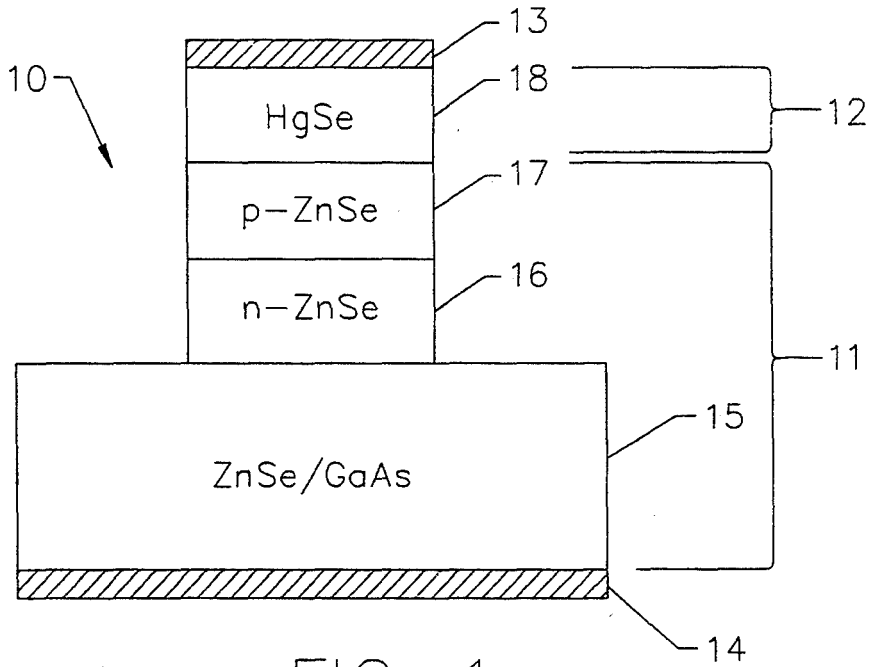


FIG. 1.

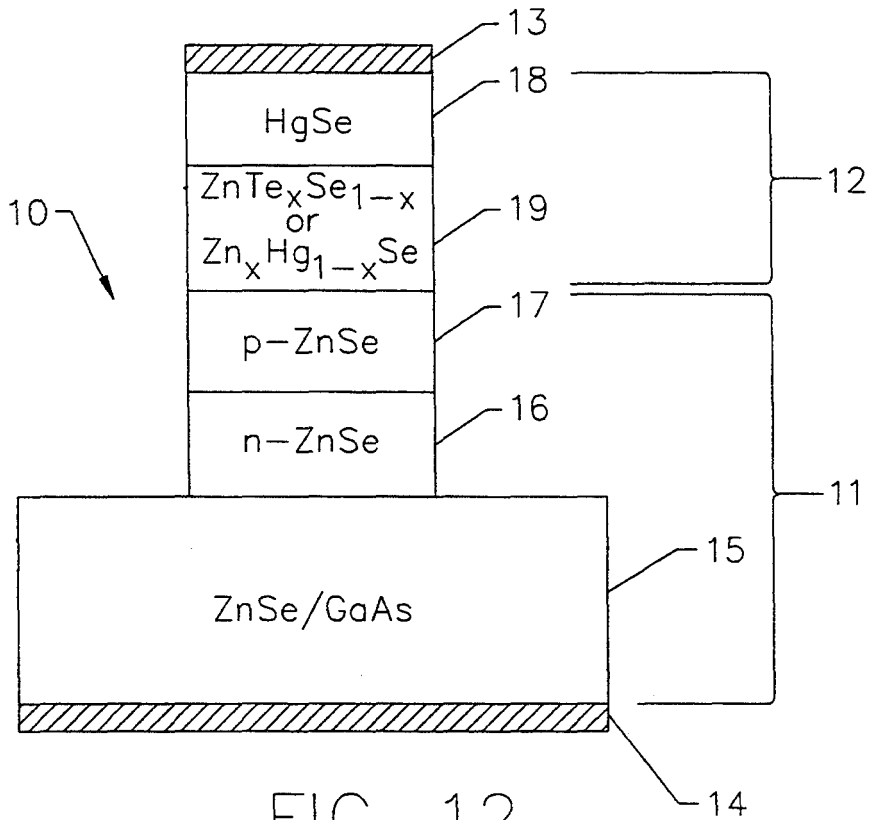


FIG. 12.

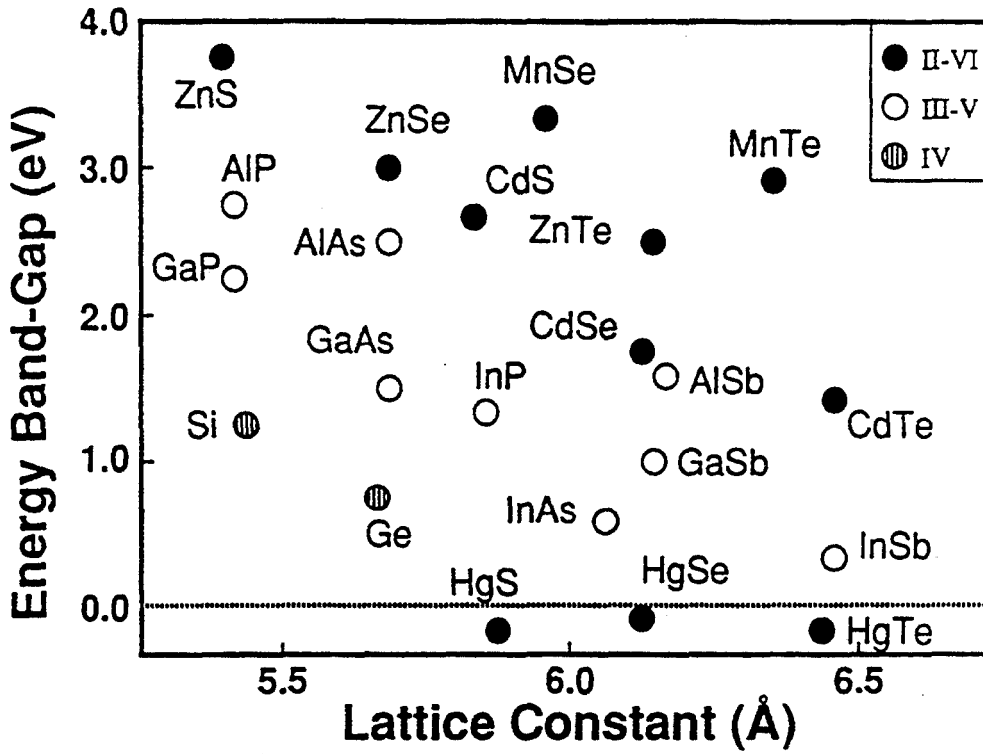


FIG. 2.

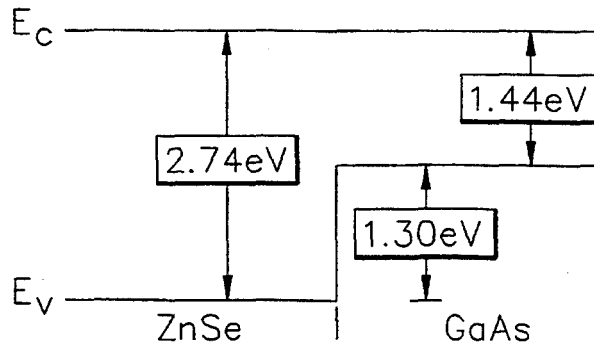


FIG. 3.

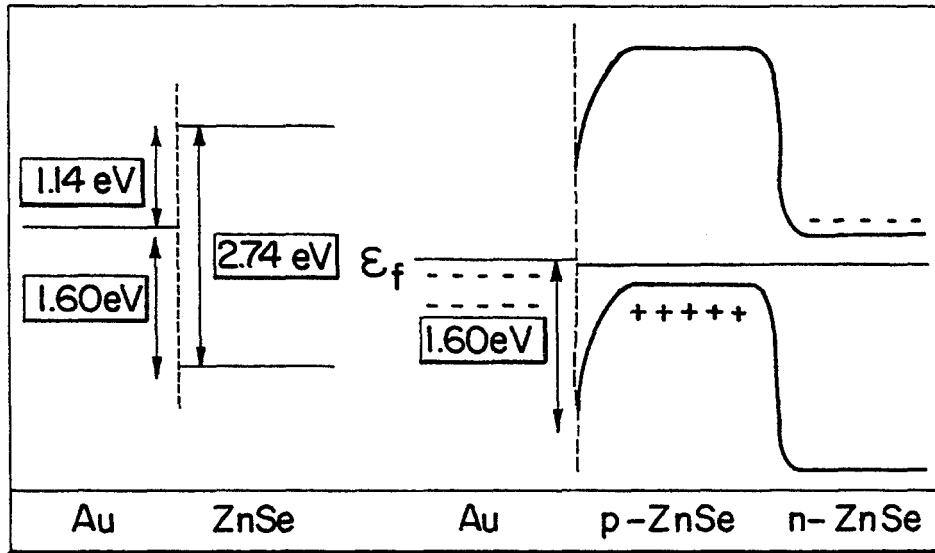


FIG. 4.

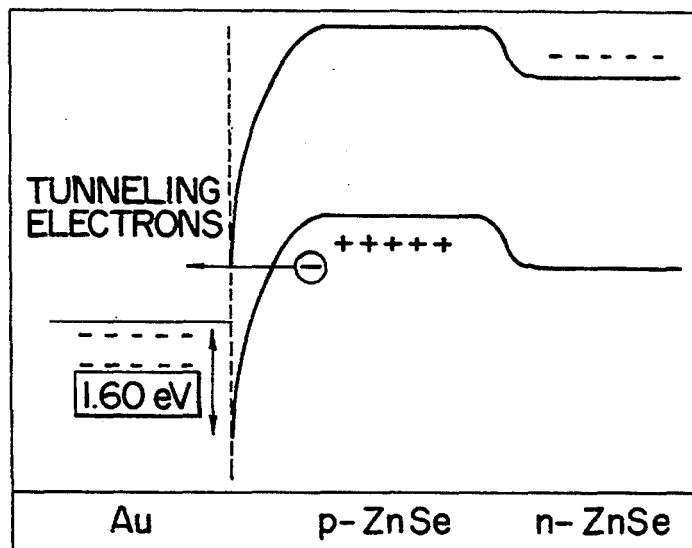


FIG. 5.

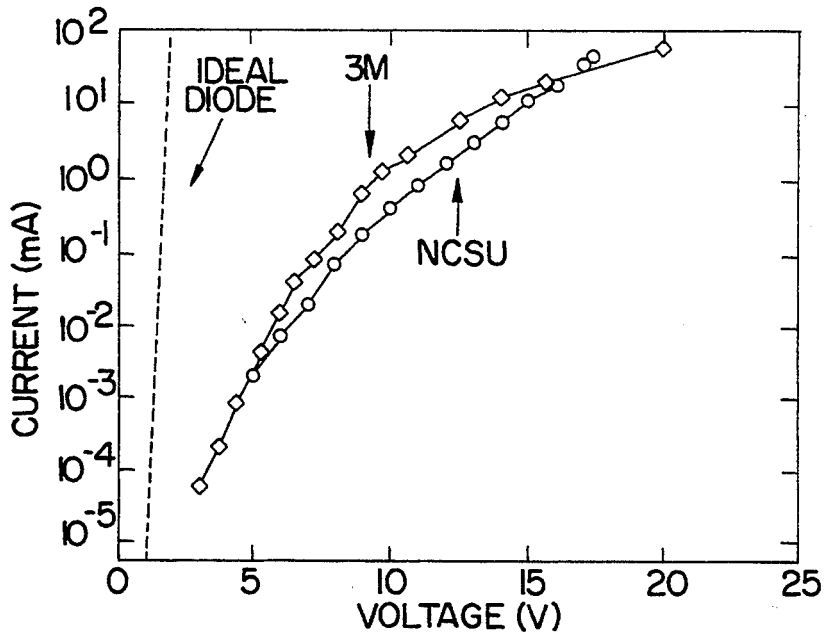


FIG. 6.

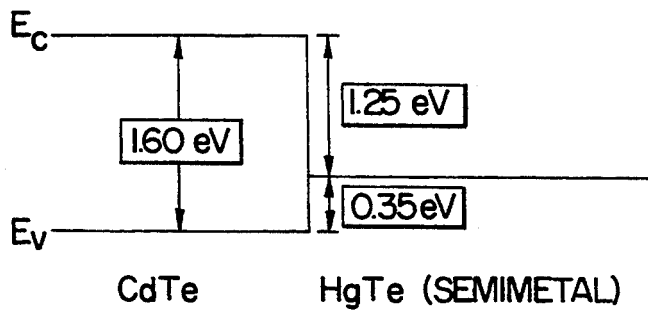


FIG. 7.

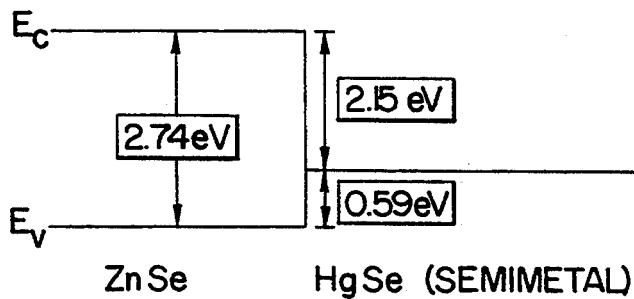


FIG. 8.

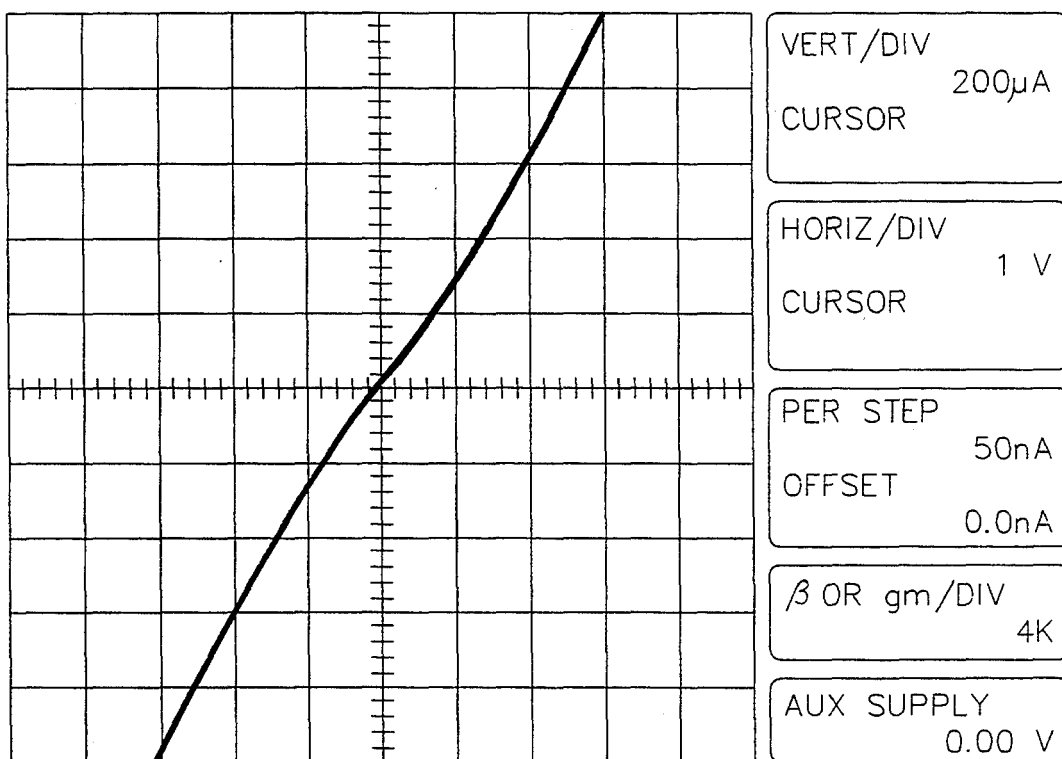


FIG. 9.

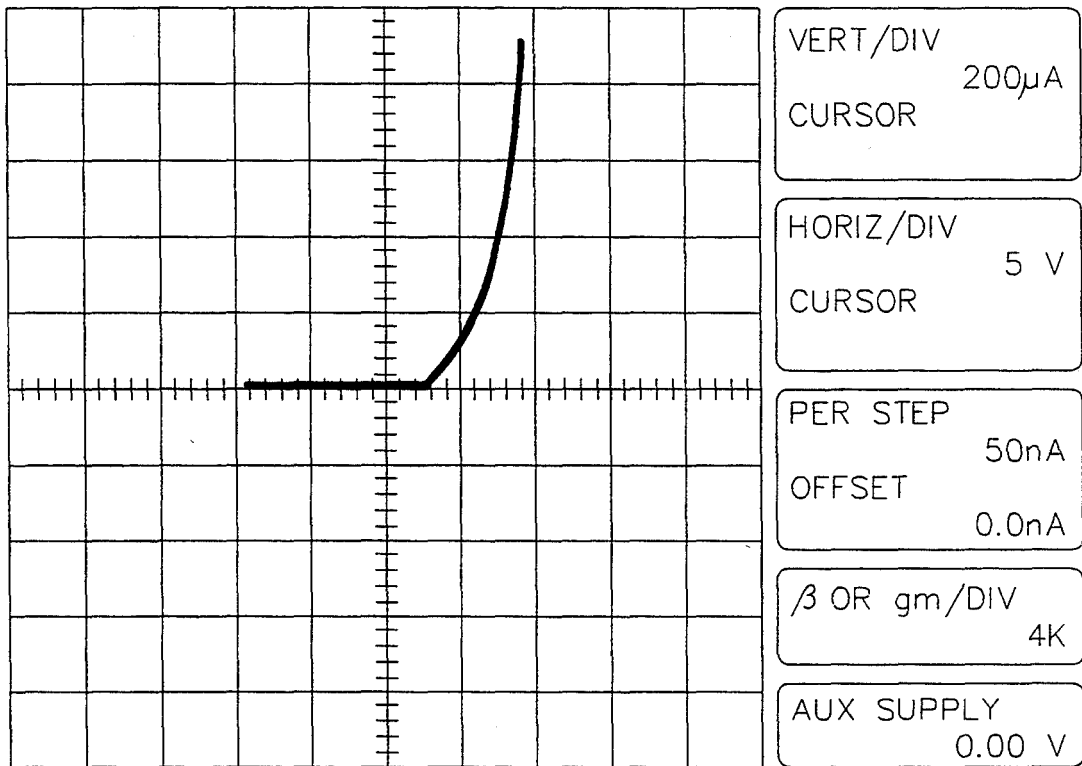


FIG. 10a.

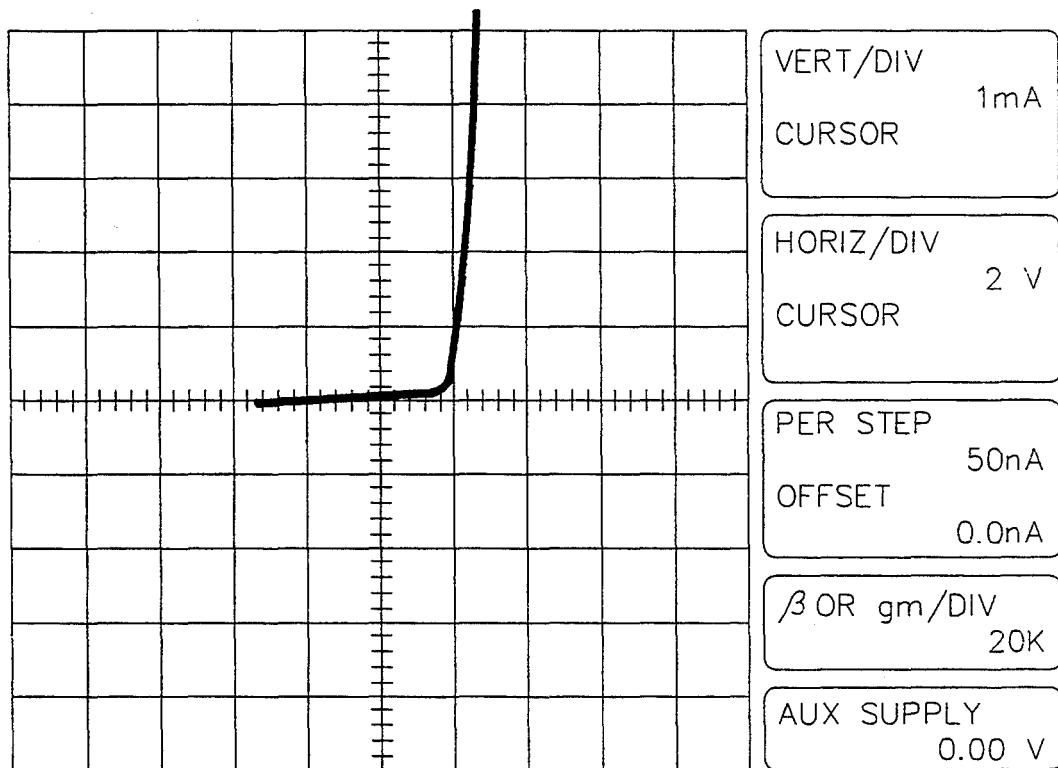


FIG. 10b.

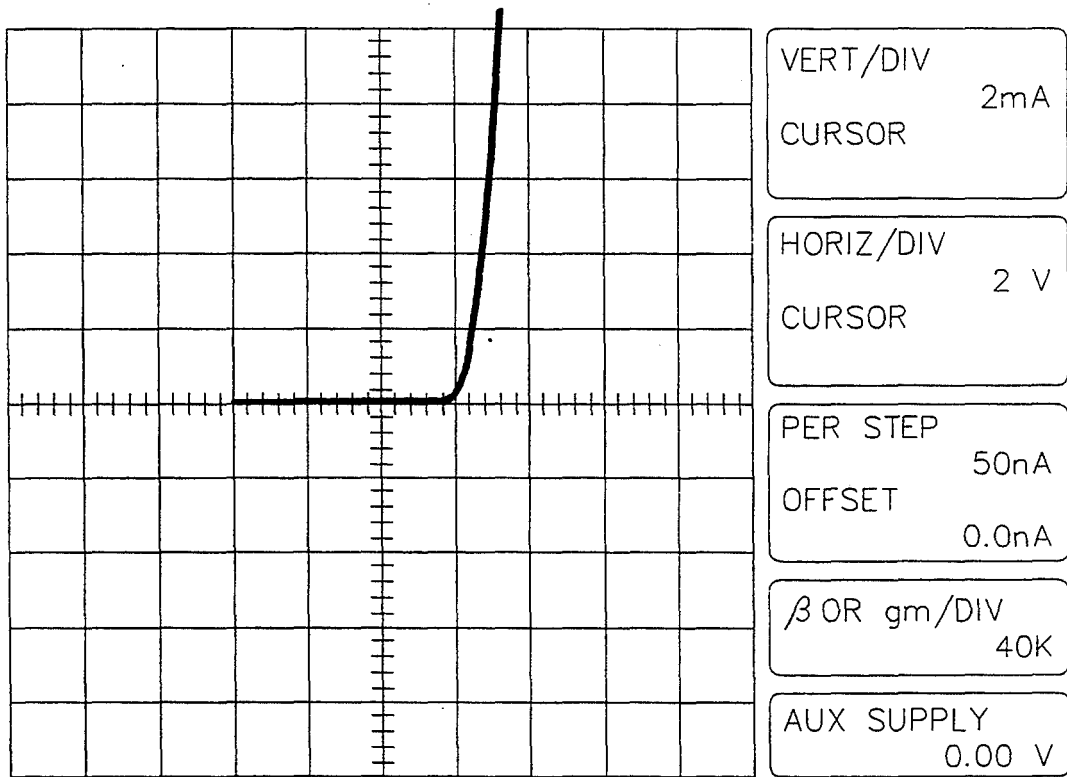


FIG. 10c.

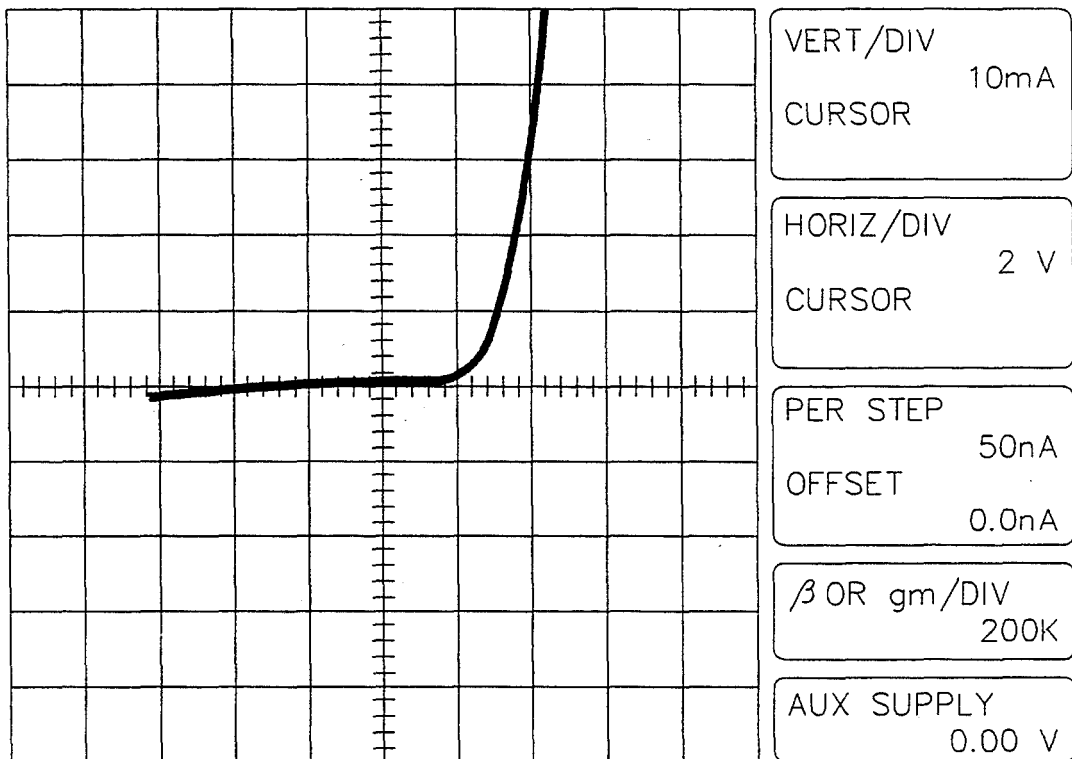


FIG. 10d.

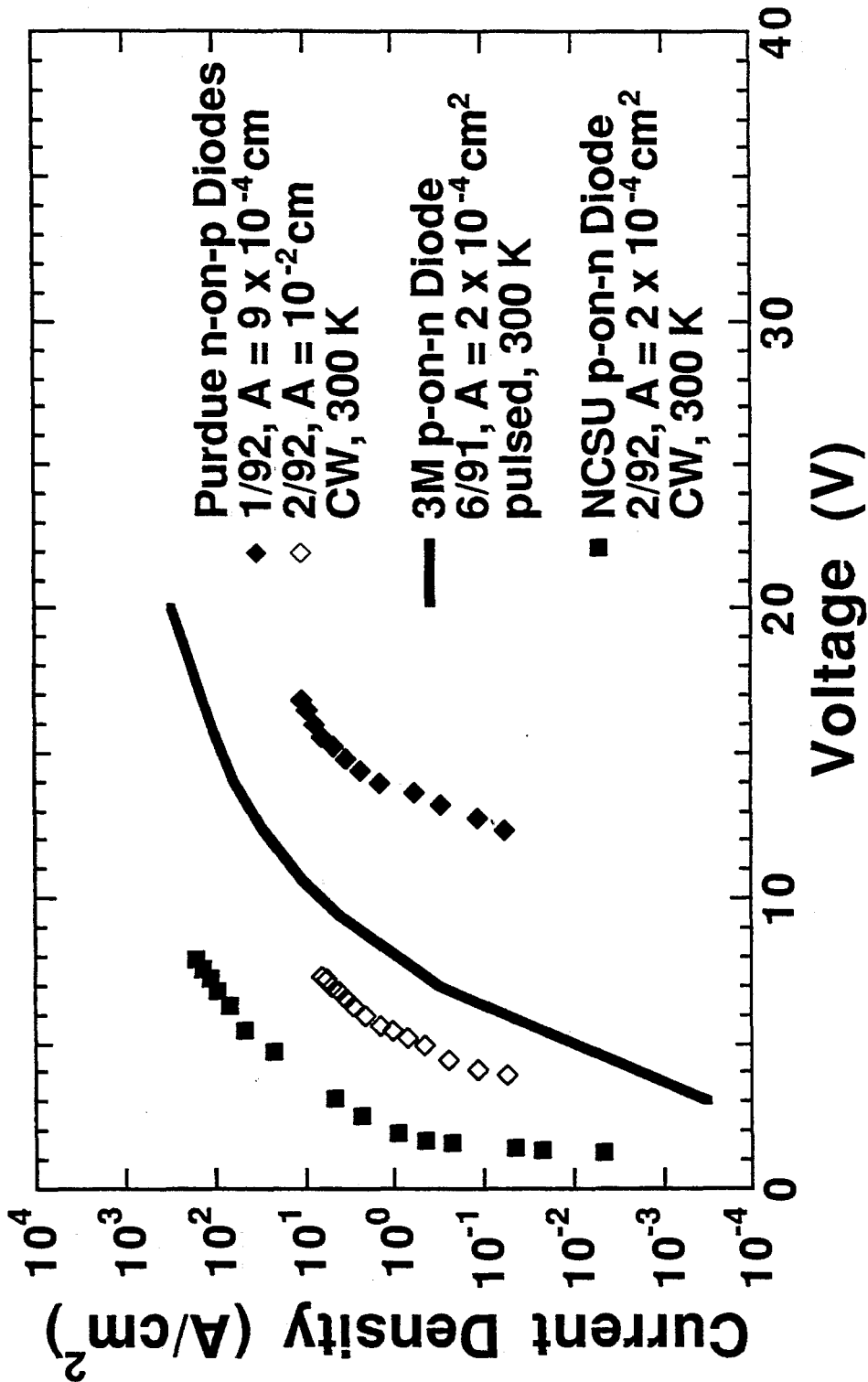


FIG. 11.

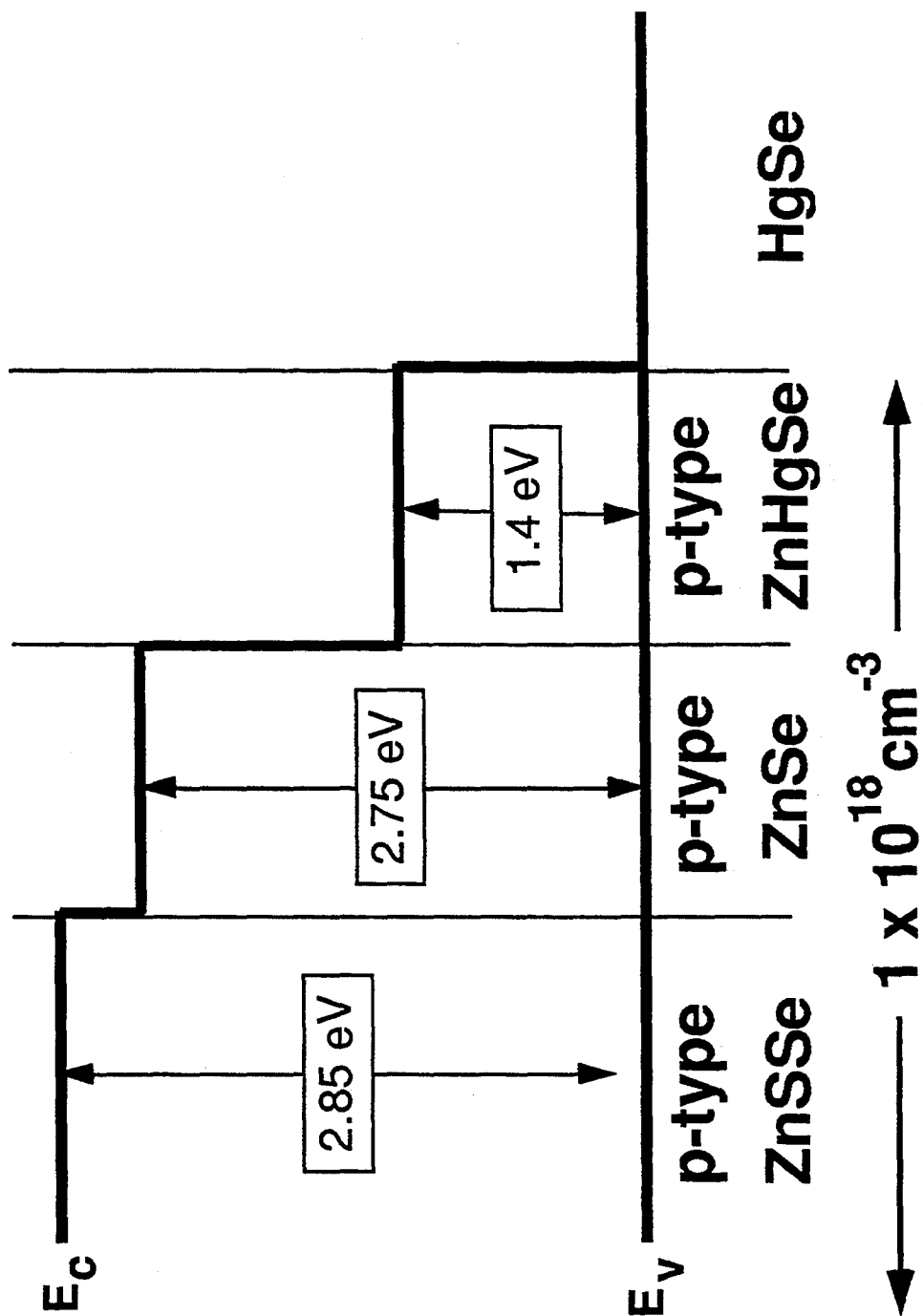


FIG. 13.

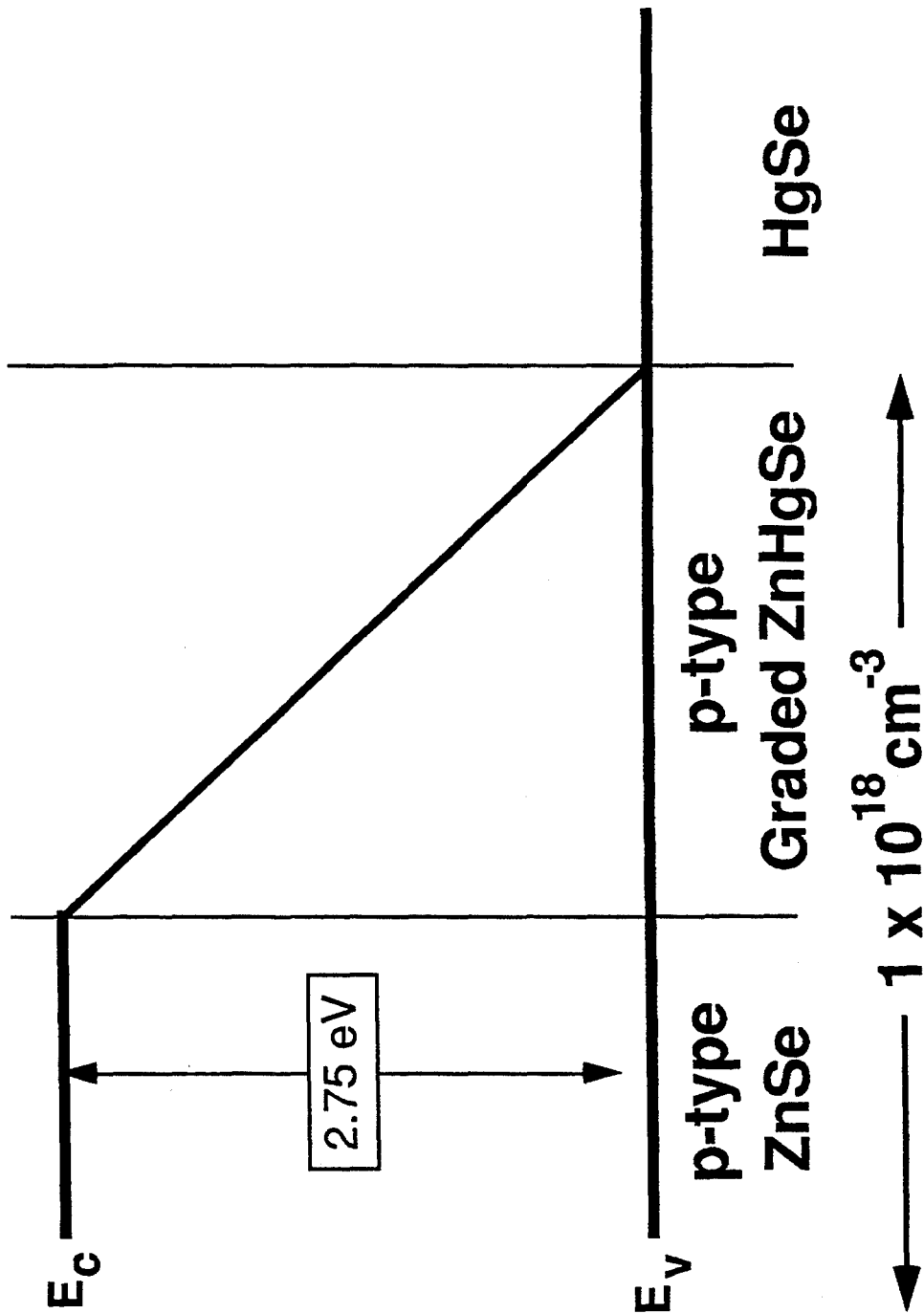


FIG. 14.

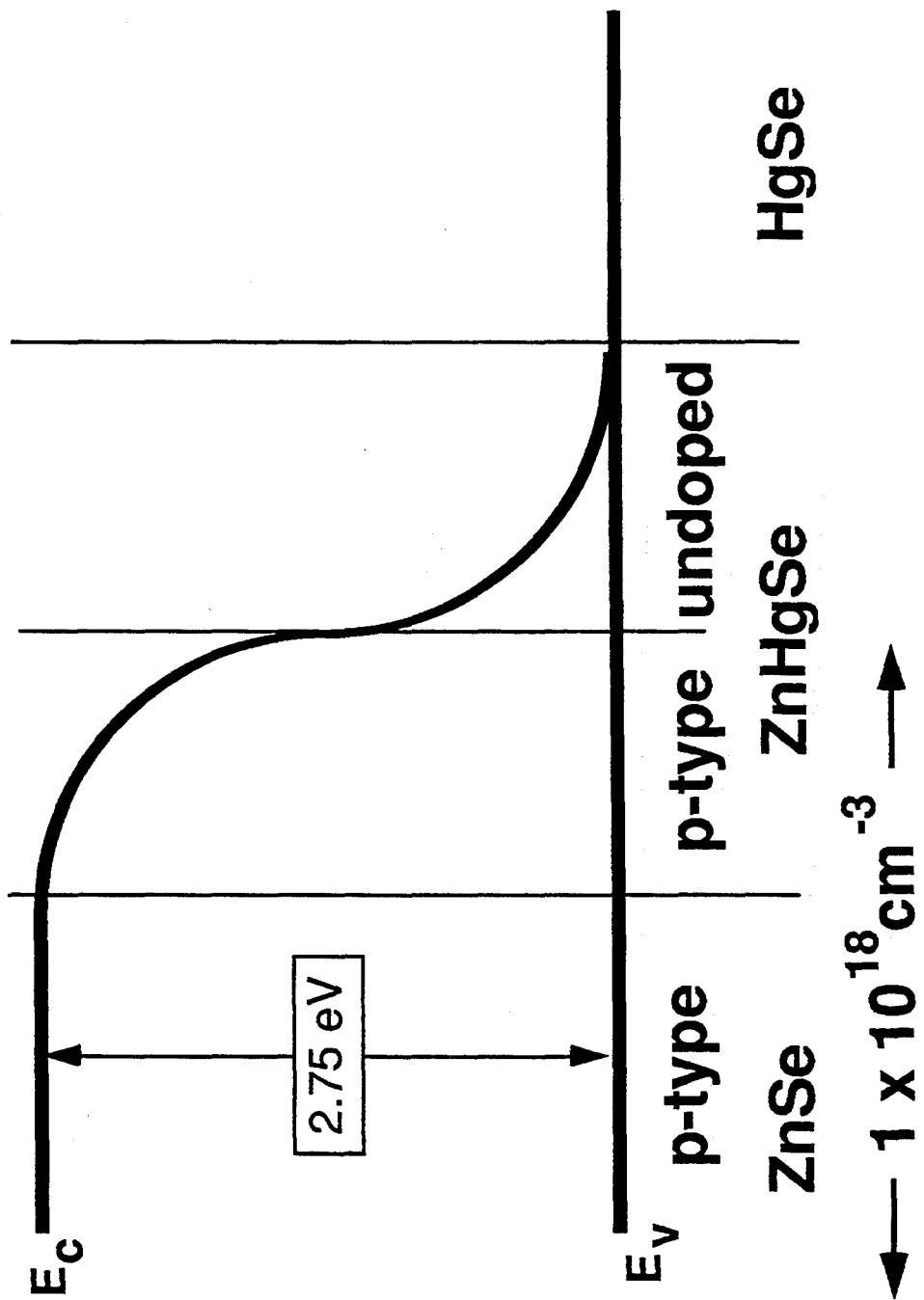


FIG. 15.

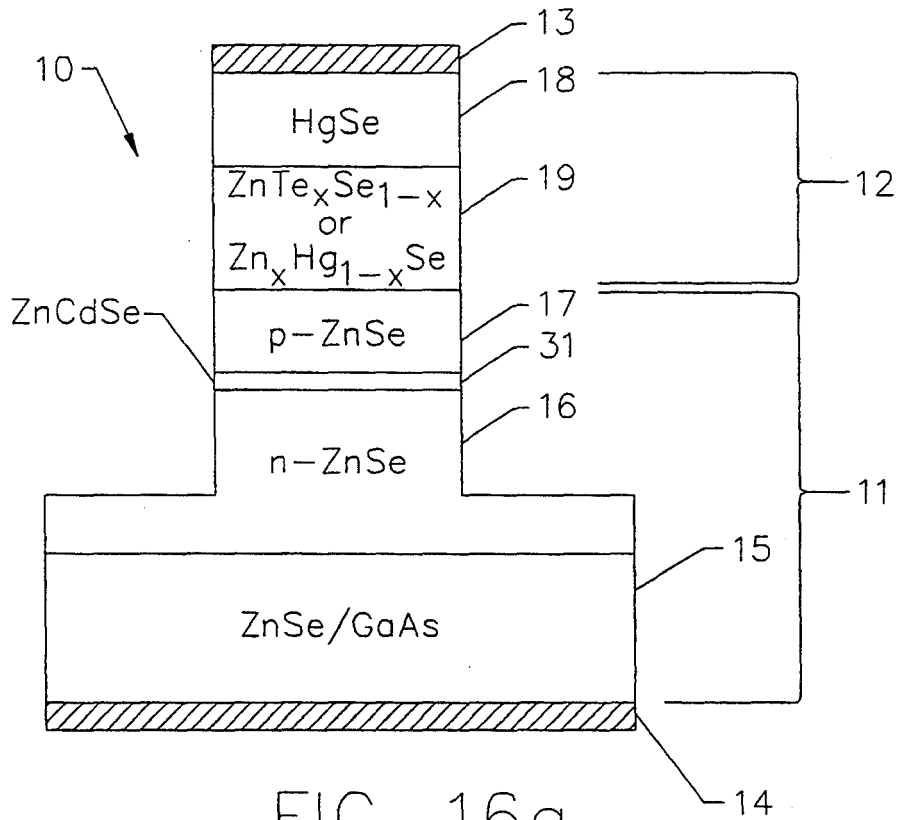


FIG. 16a.

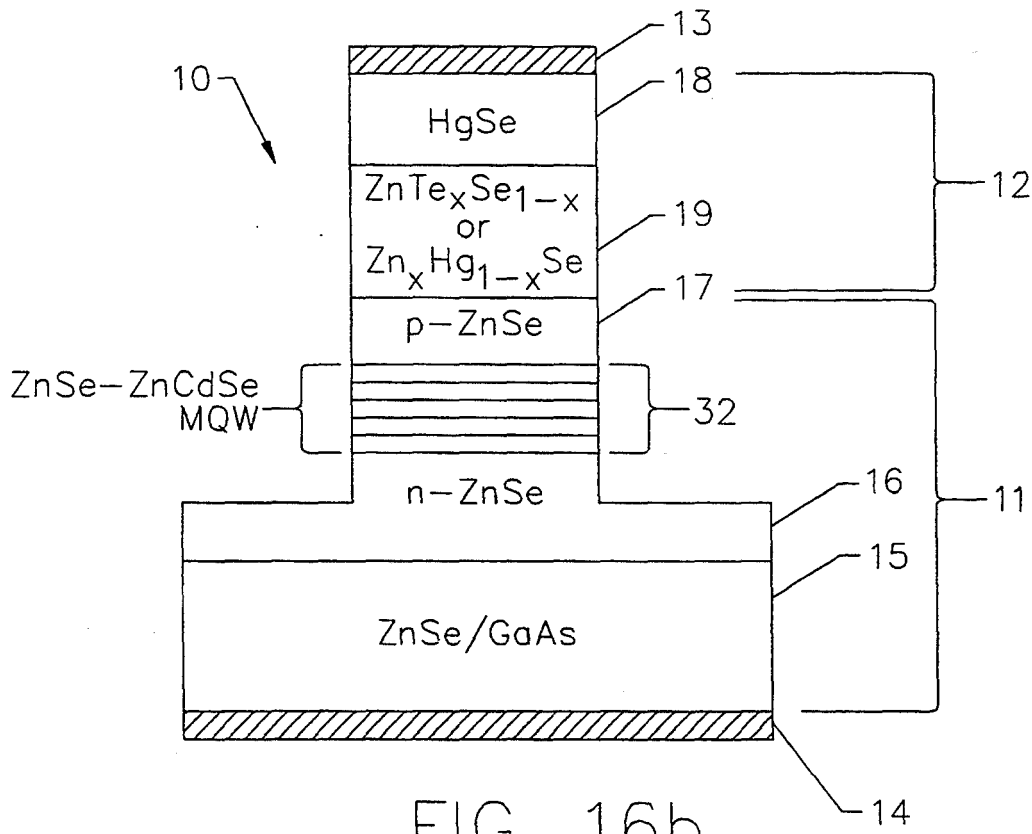


FIG. 16b.

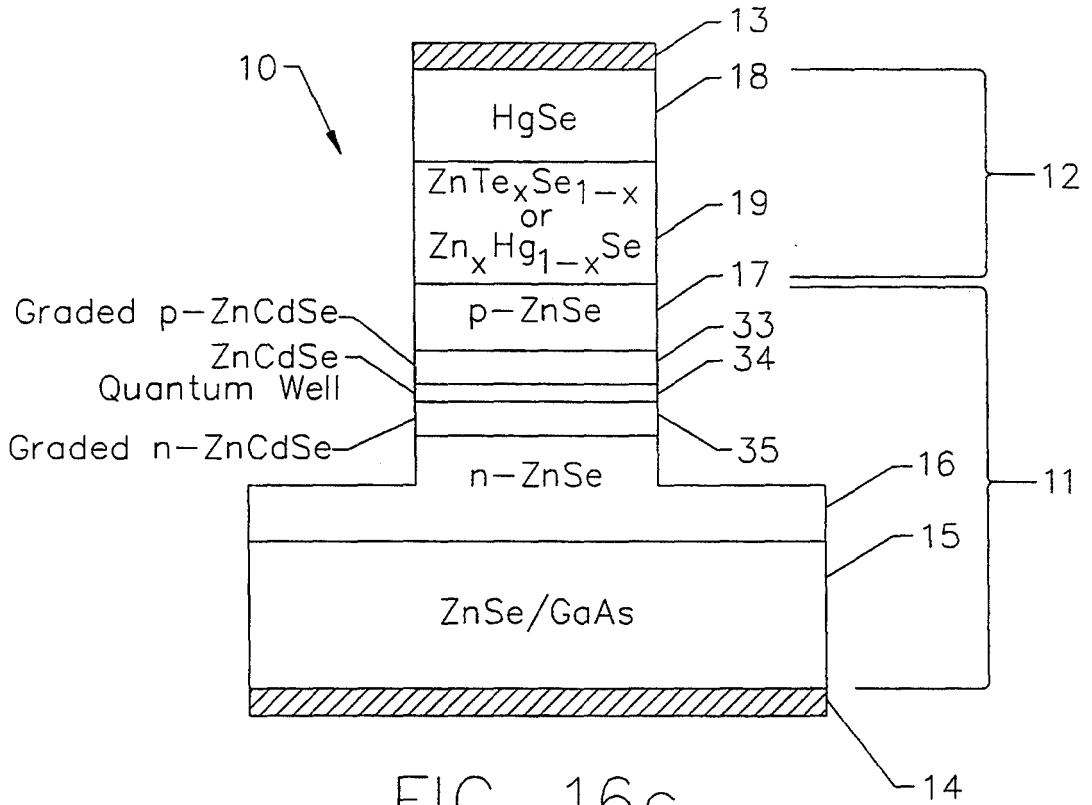


FIG. 16c.

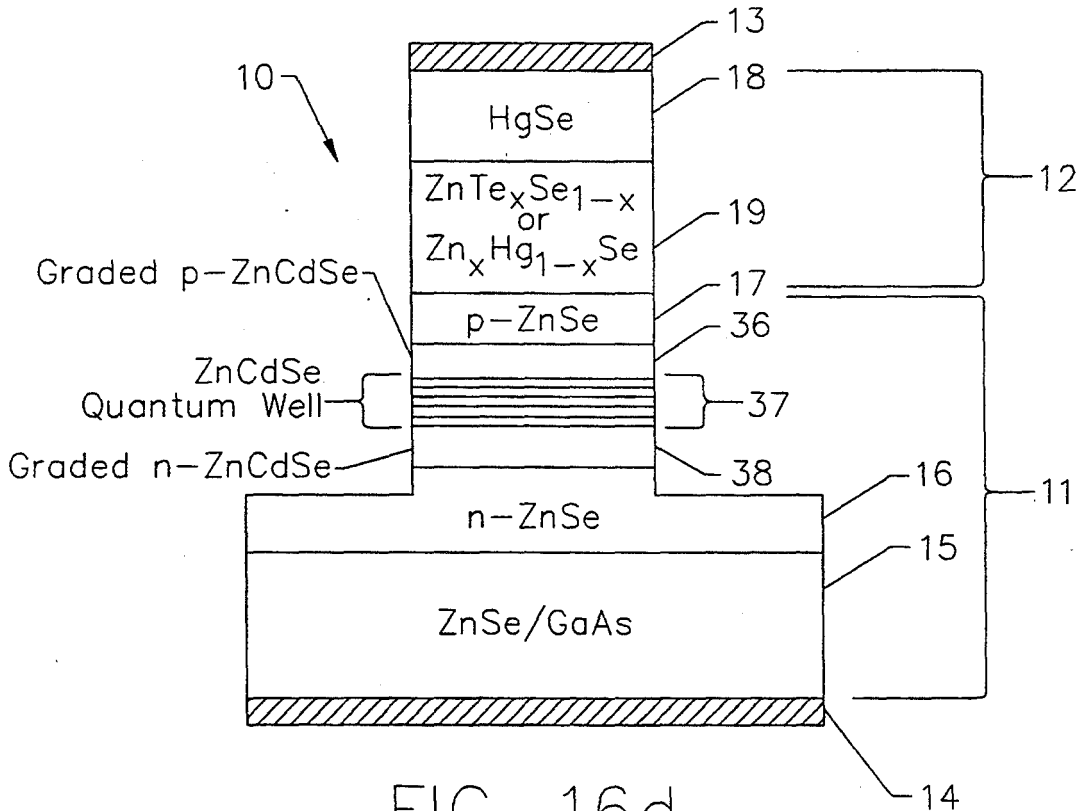


FIG. 16d.

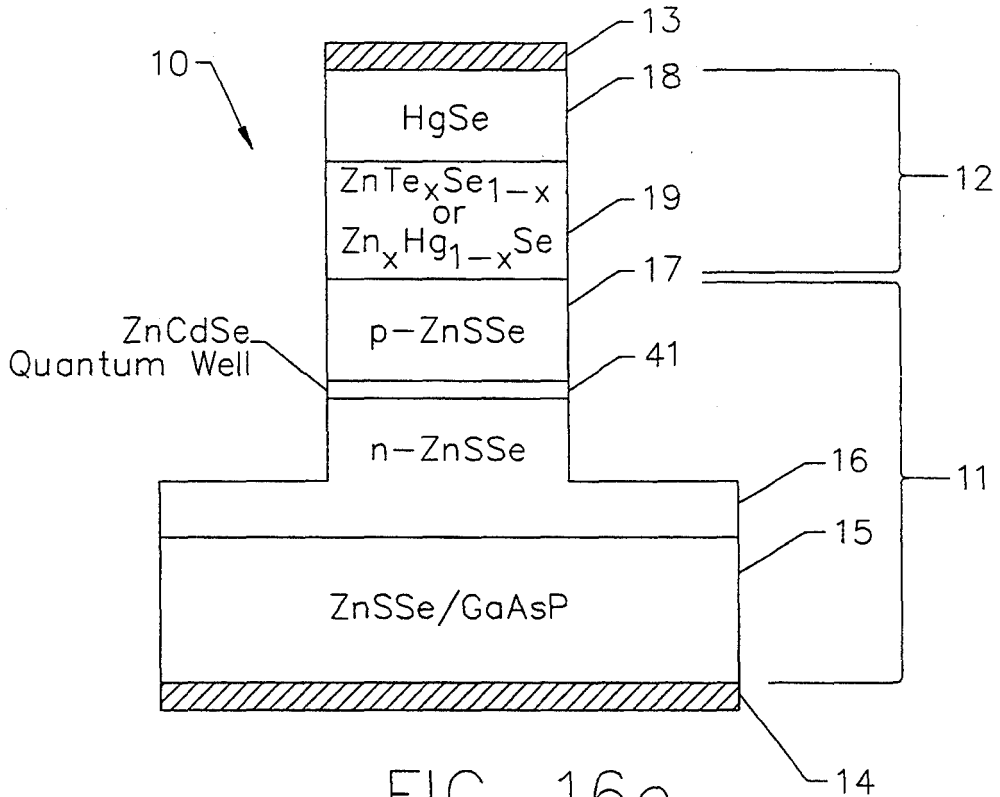


FIG. 16e.

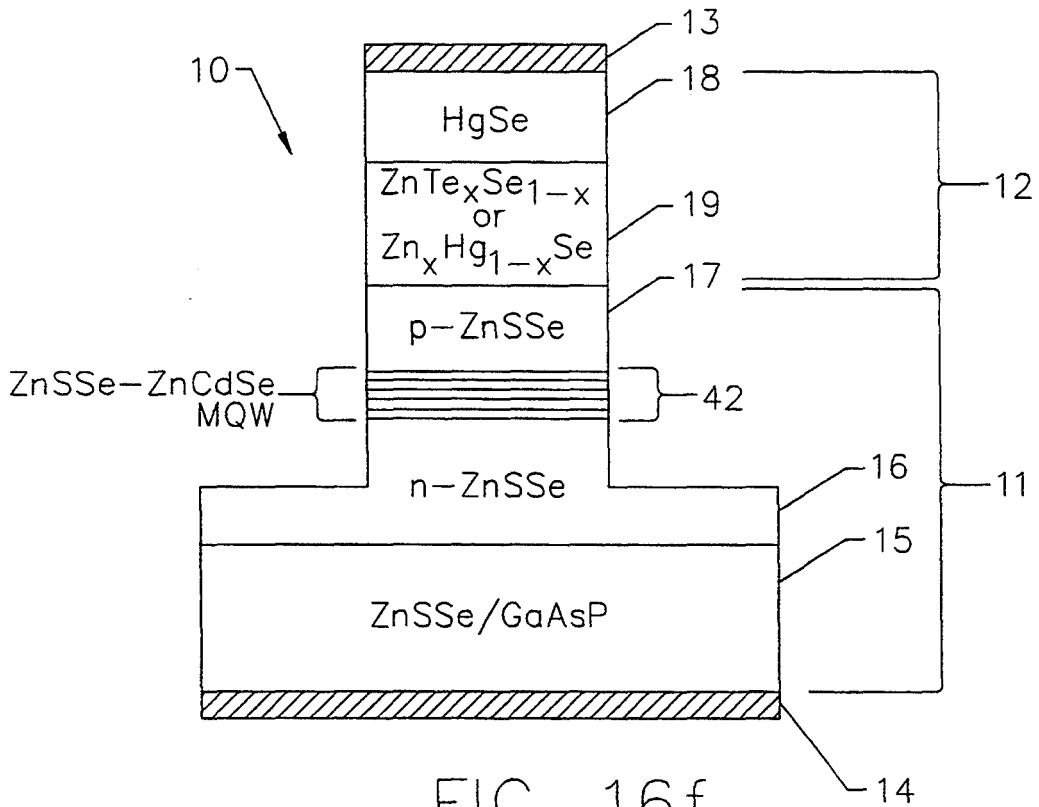


FIG. 16f.

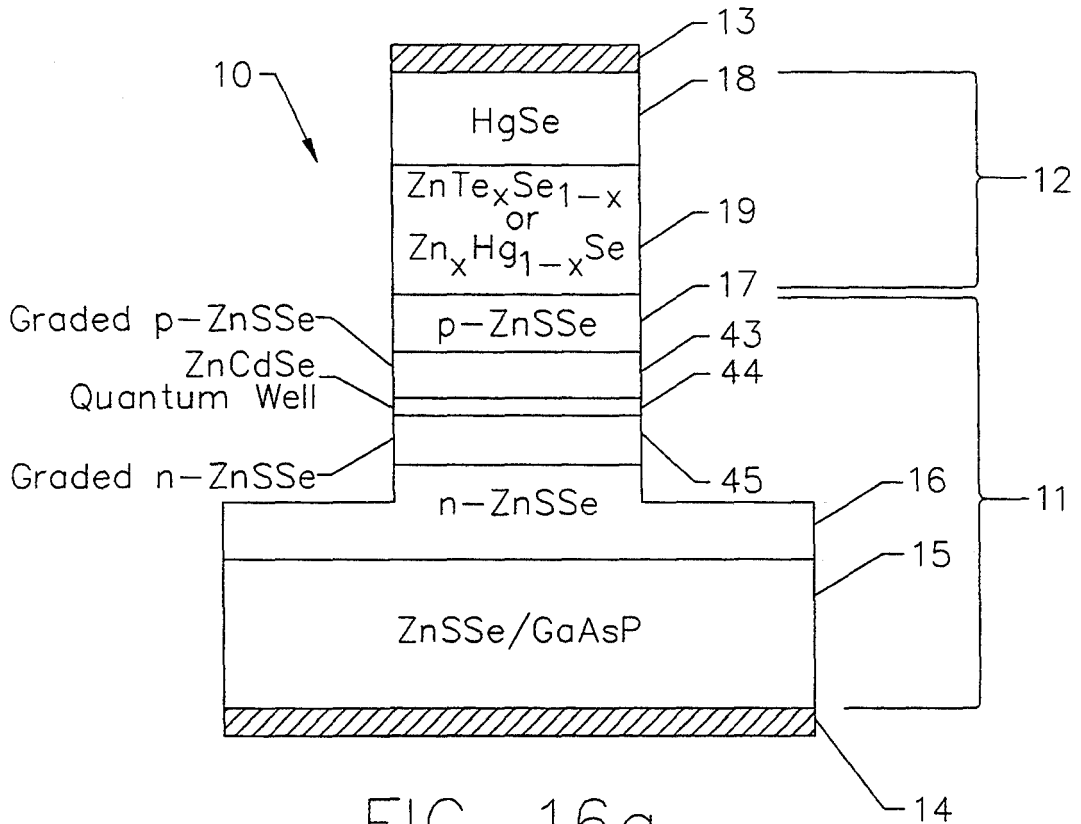


FIG. 16g.

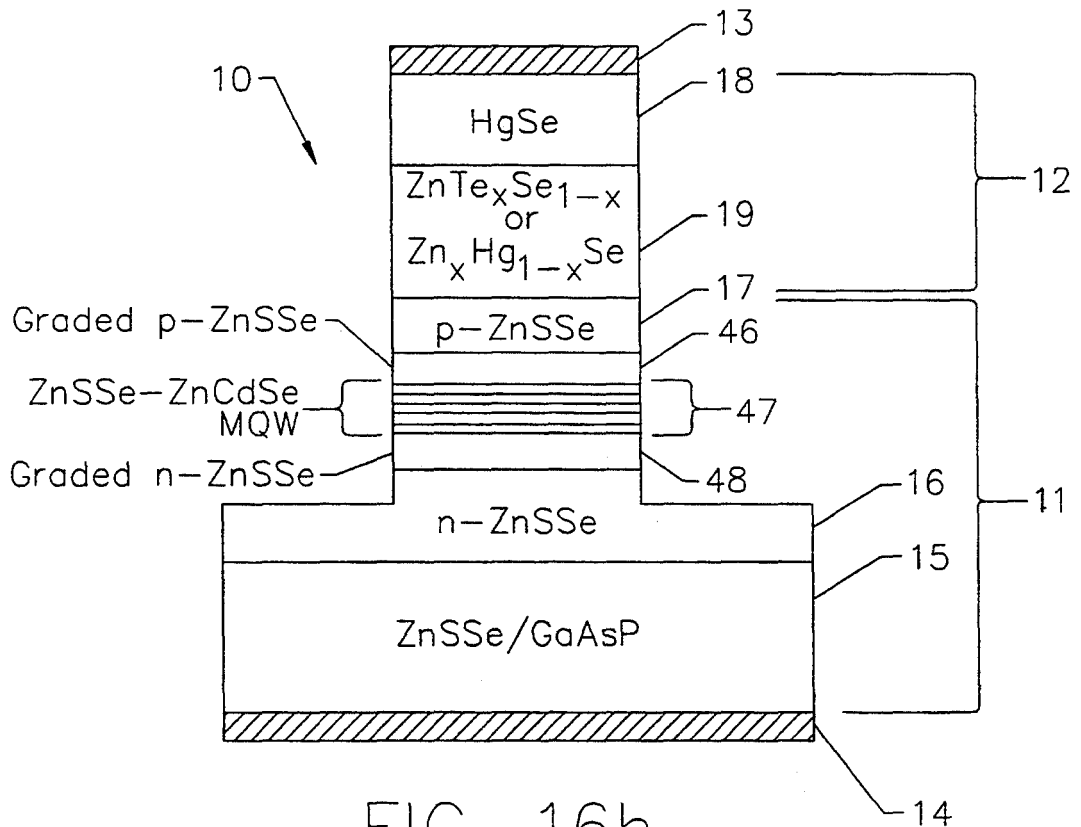


FIG. 16h.

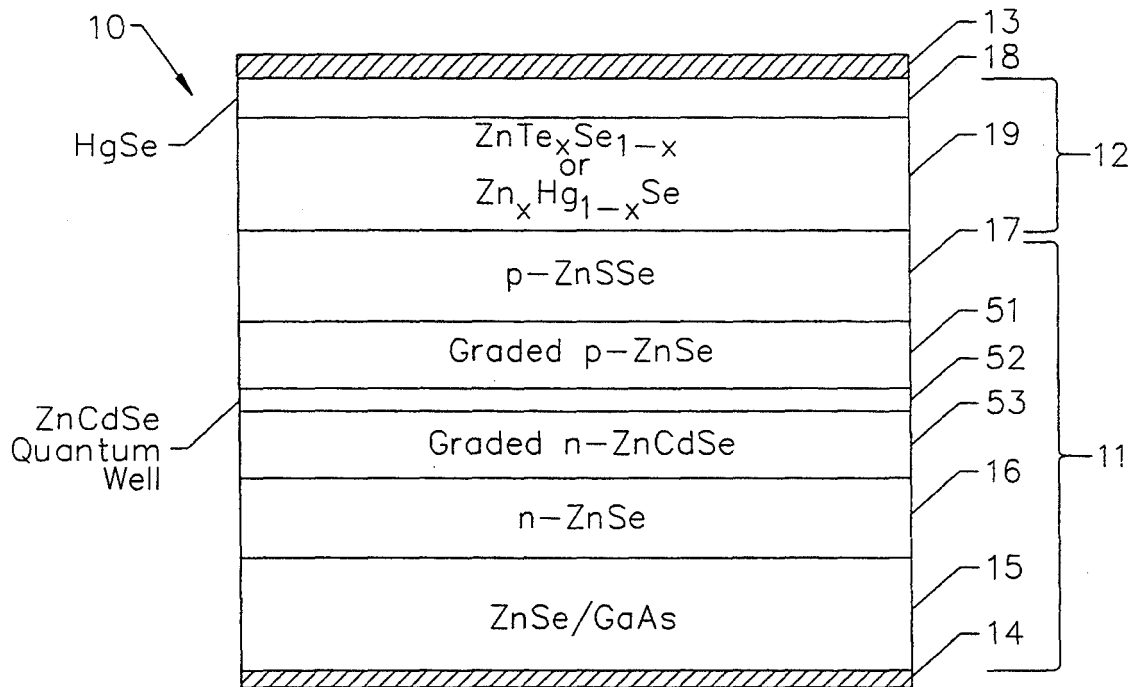


FIG. 16i.

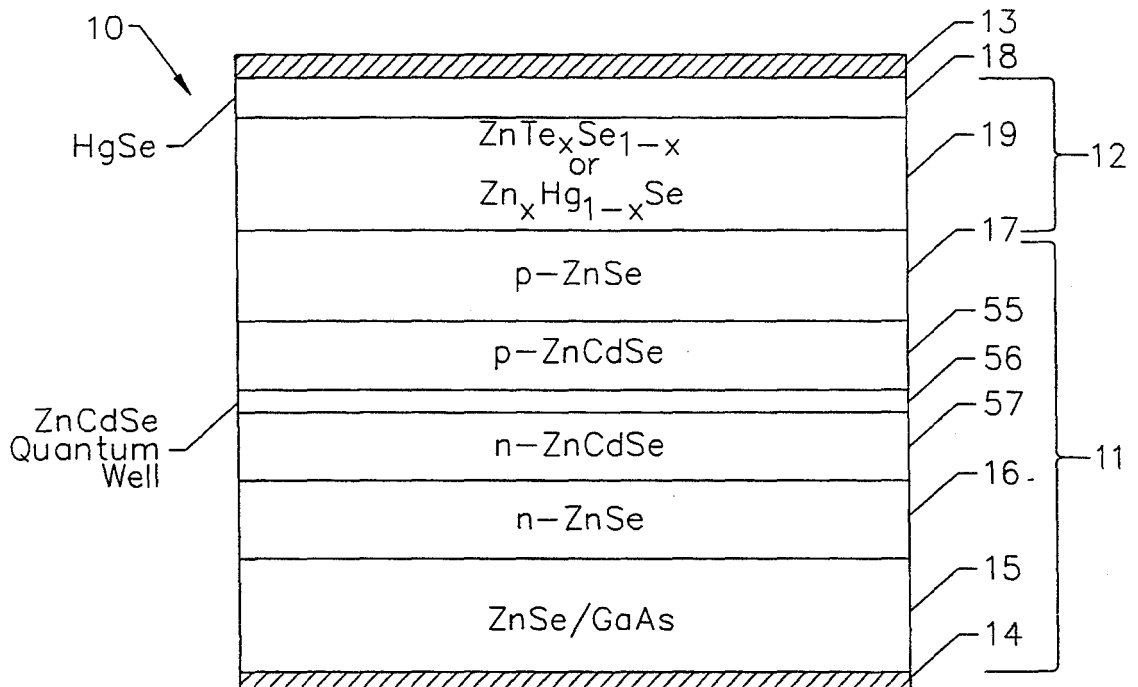


FIG. 16j.

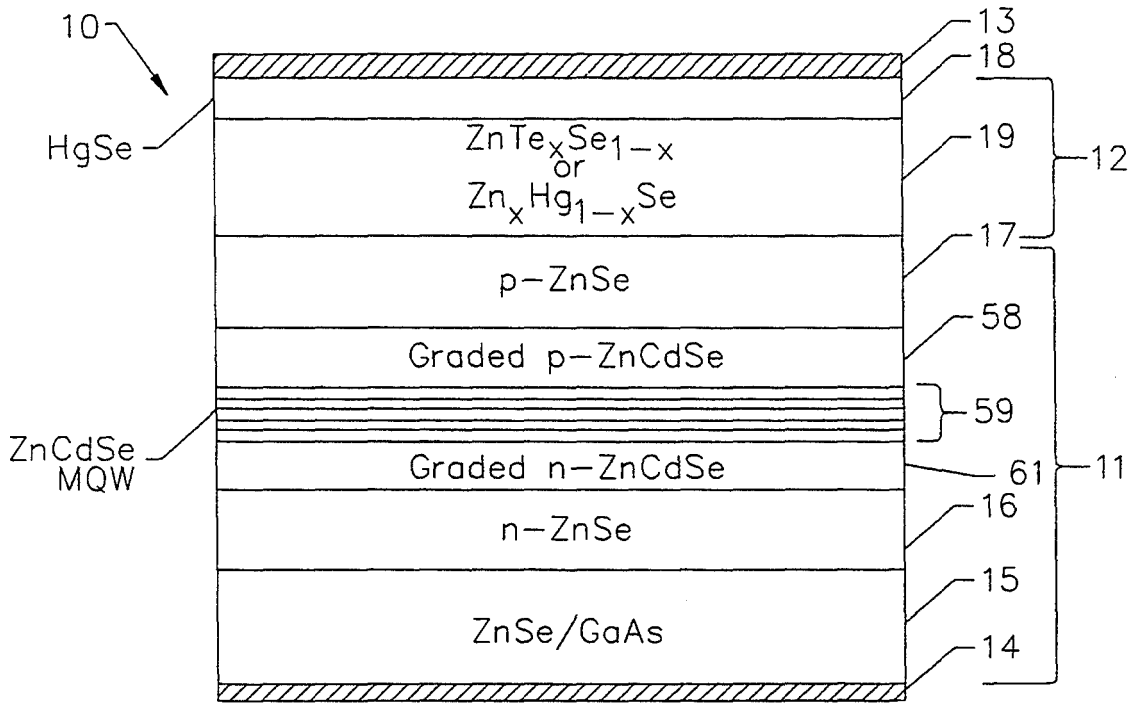


FIG. 16k.

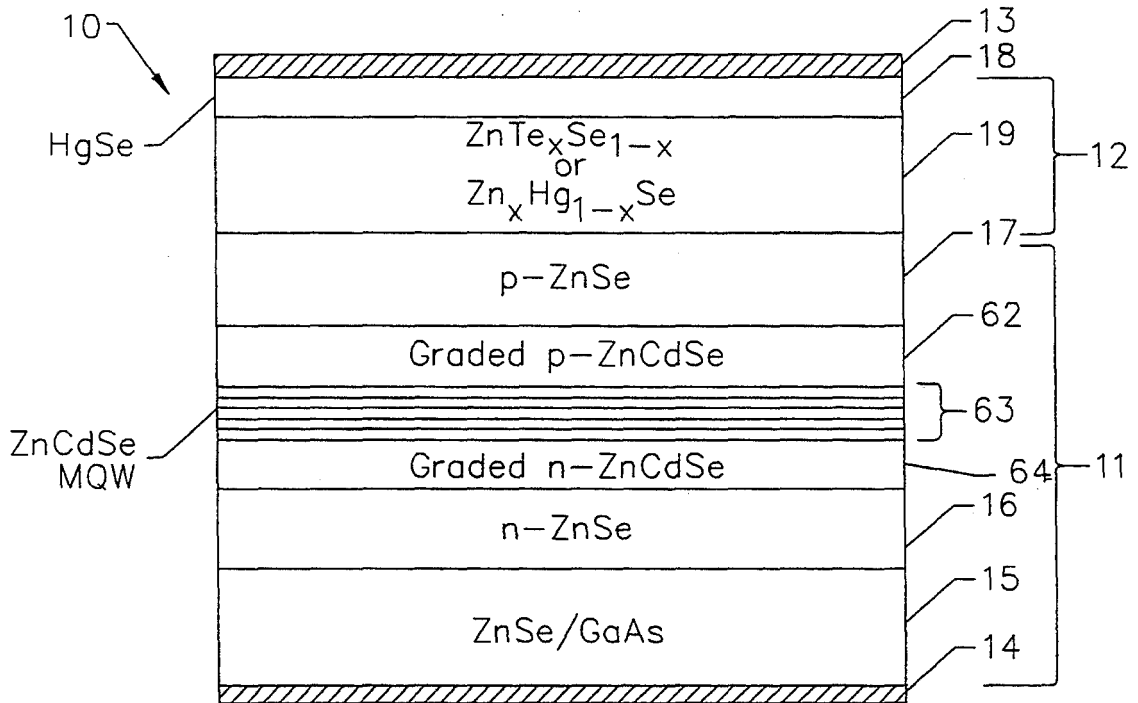


FIG. 16l.

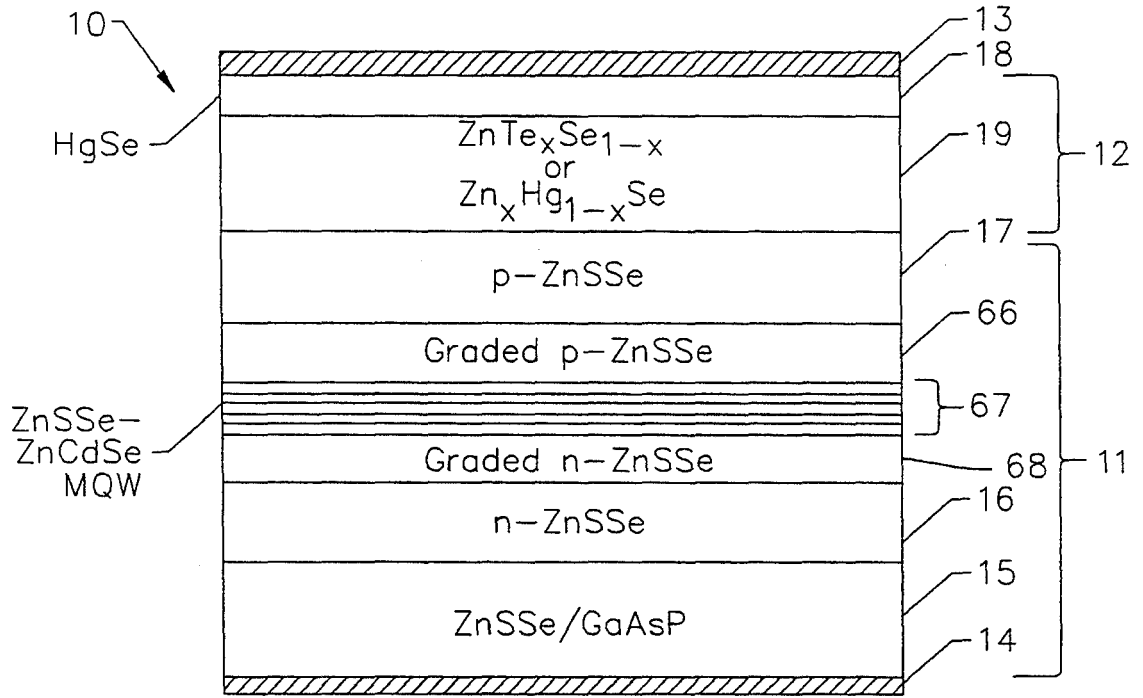


FIG. 16m.

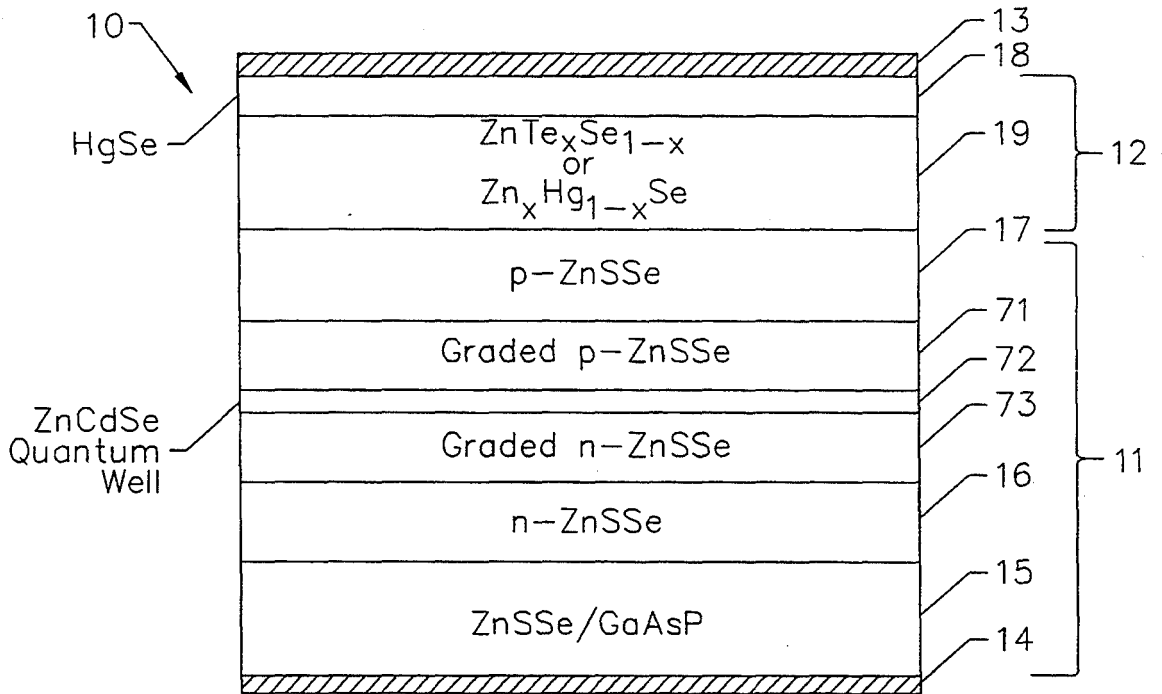


FIG. 16n.

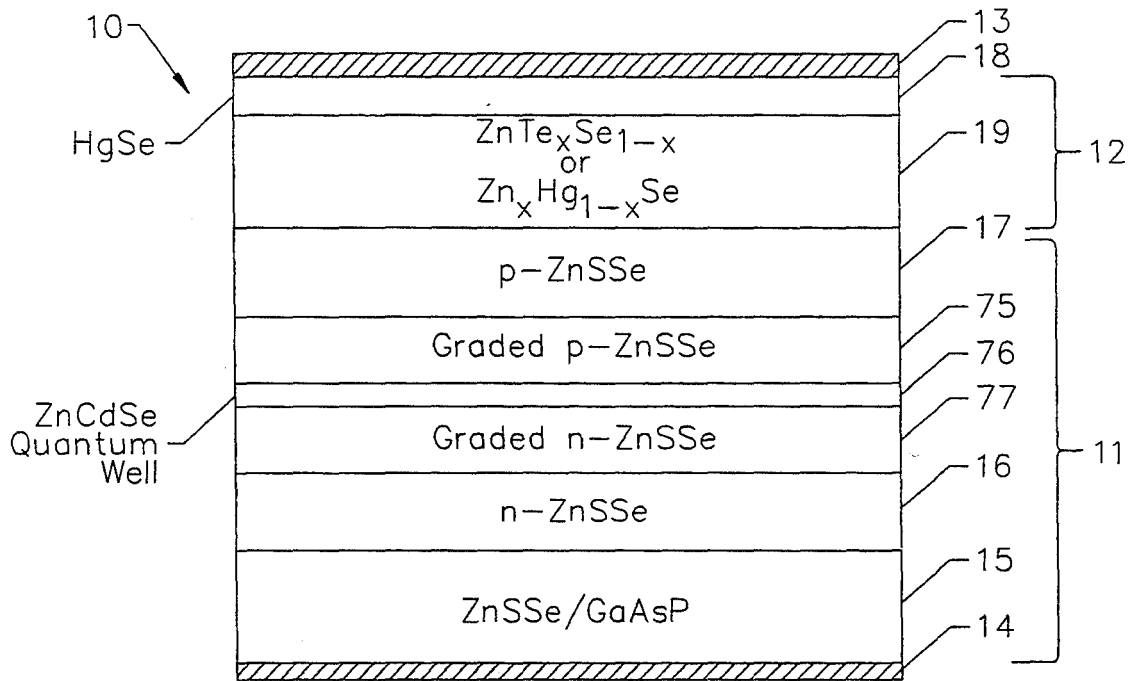


FIG. 16o.

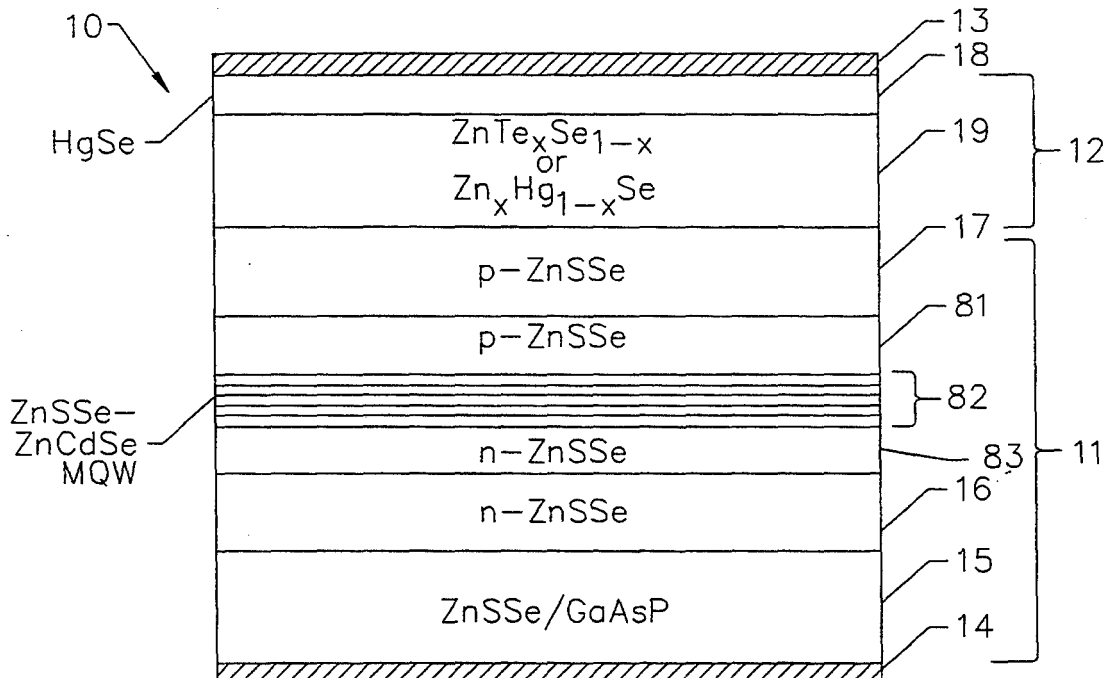


FIG. 16p.

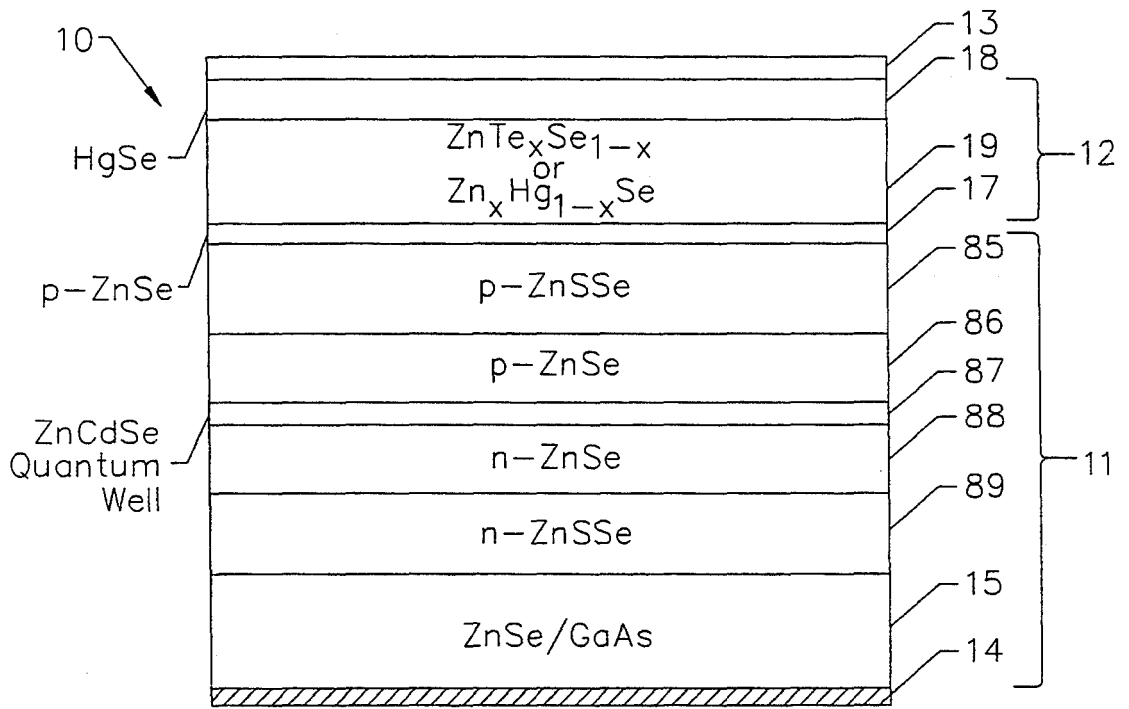


FIG. 17.

FIG. 18a.

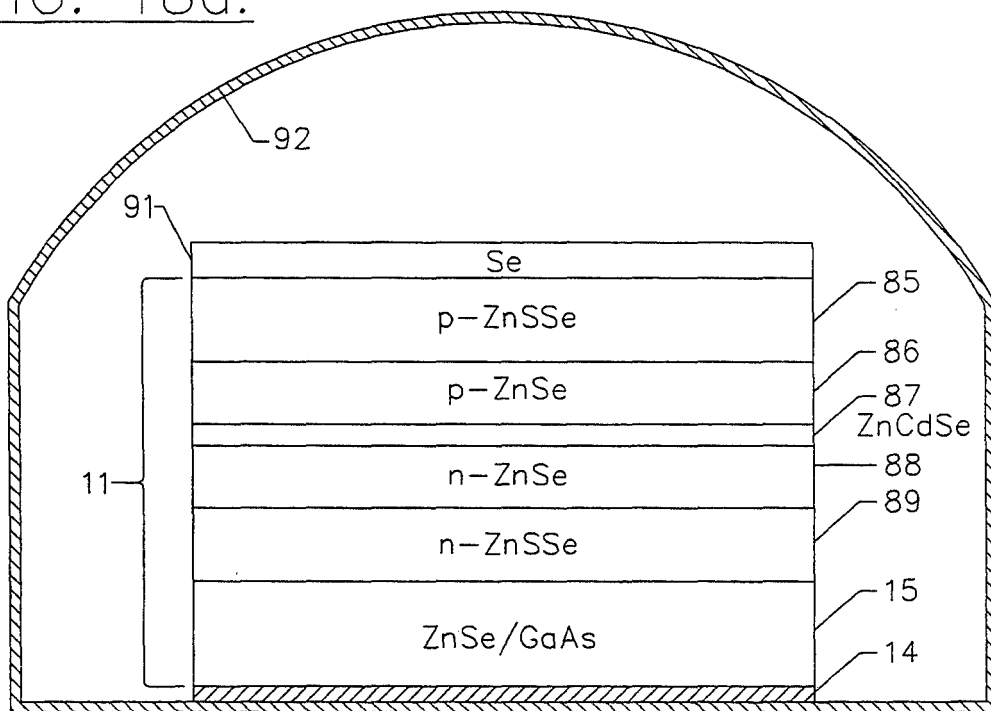


FIG. 18b.

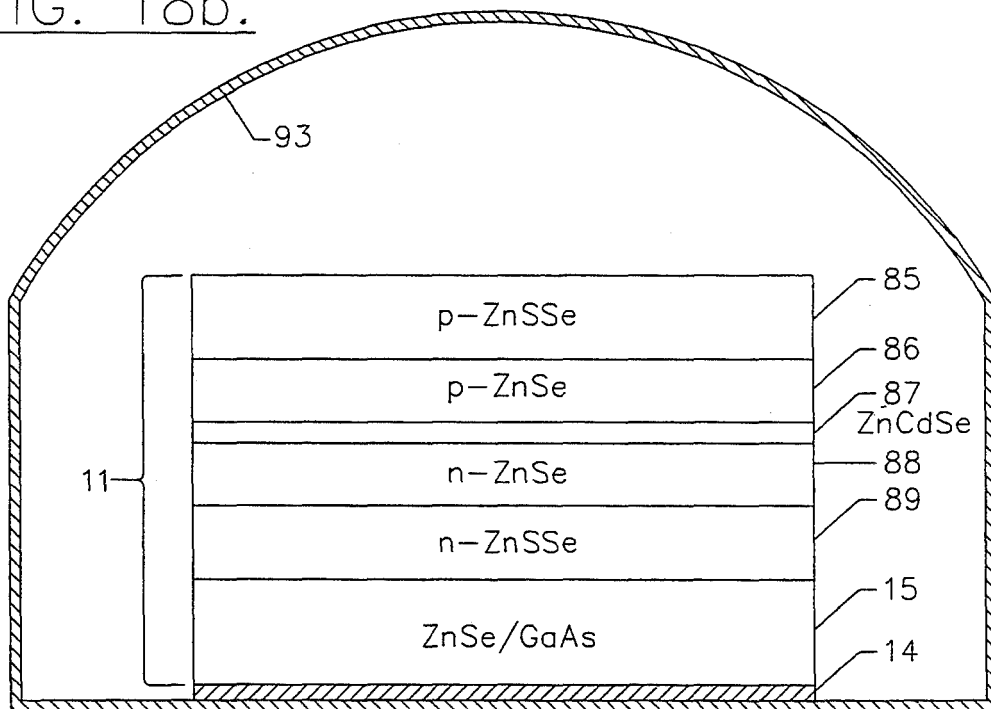


FIG. 19a.

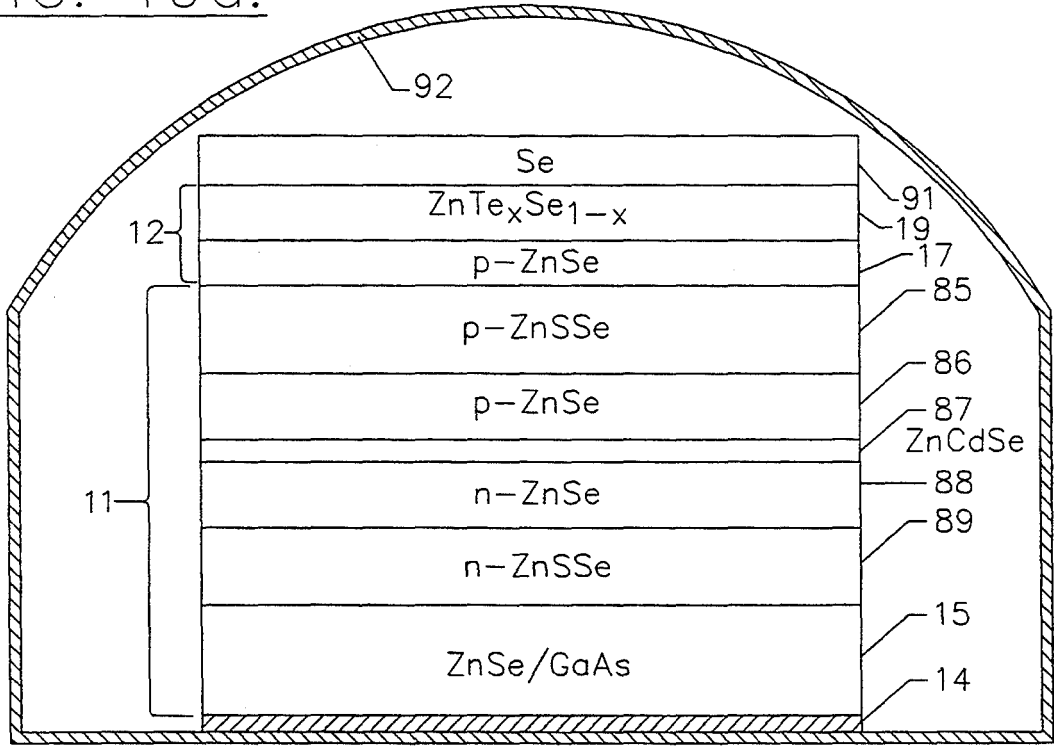
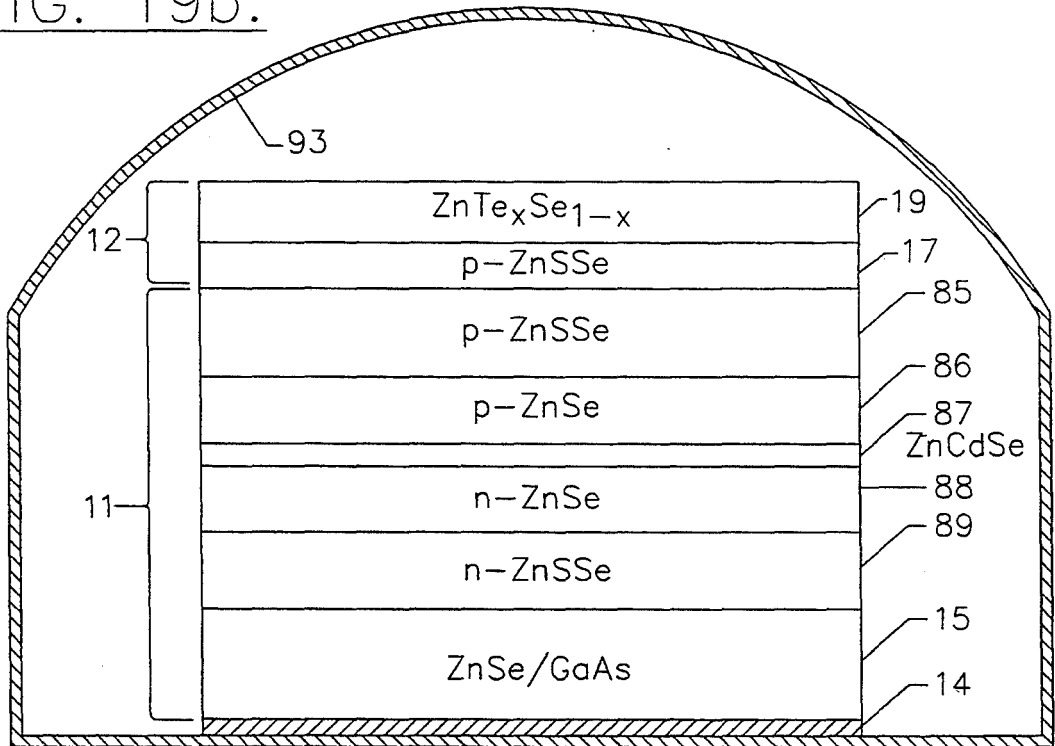


FIG. 19b.



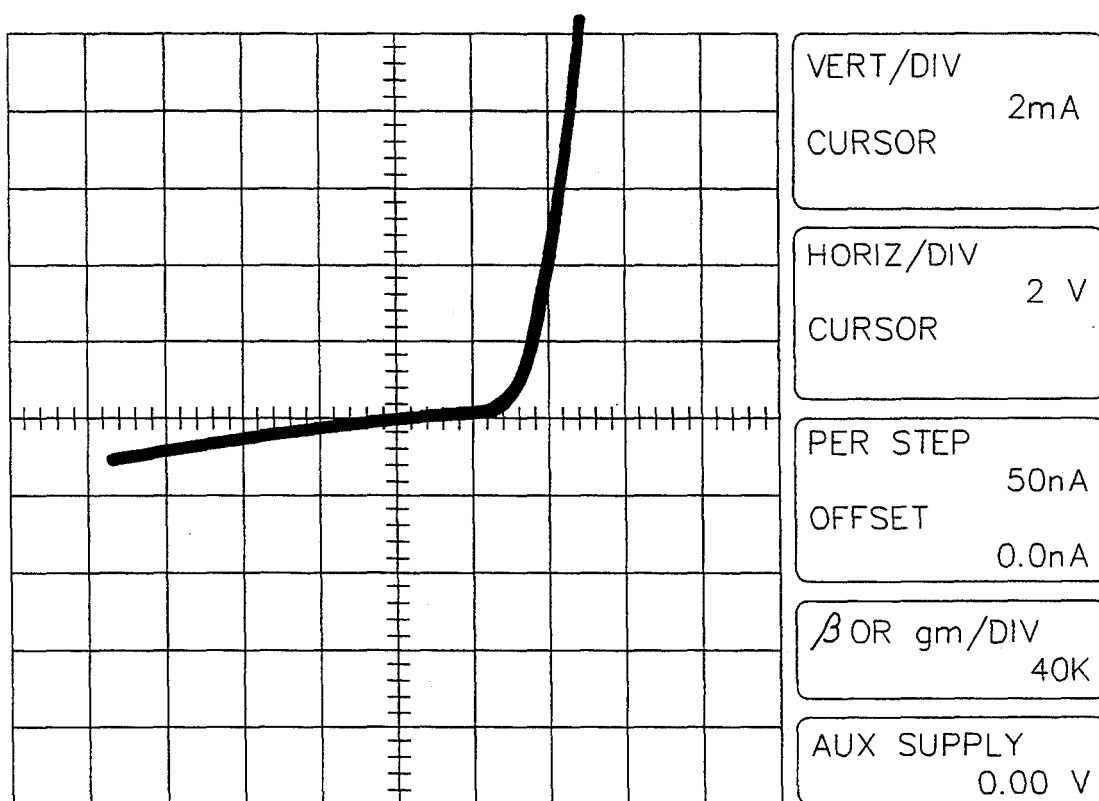


FIG. 20.

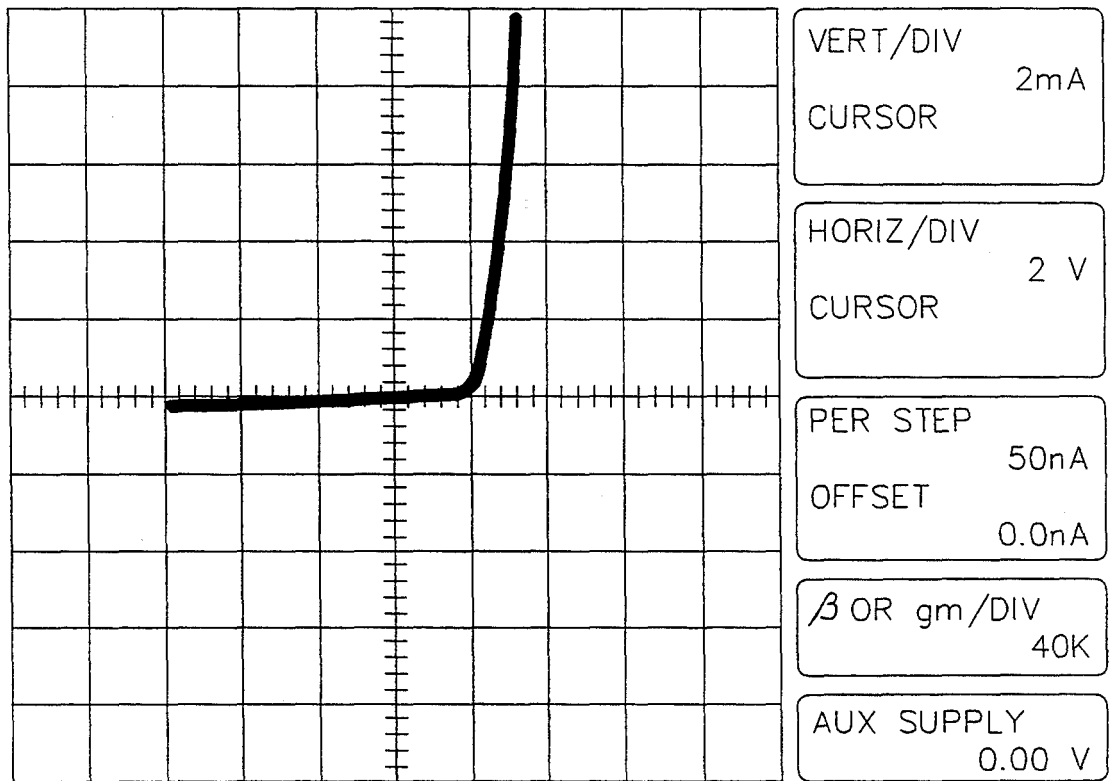


FIG. 21.

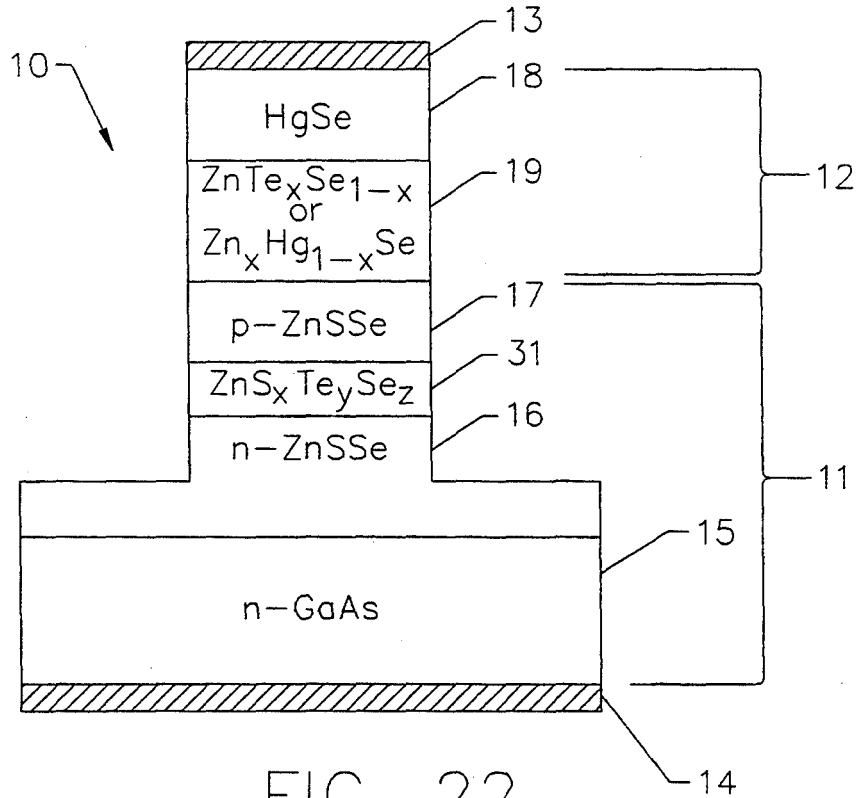


FIG. 22.

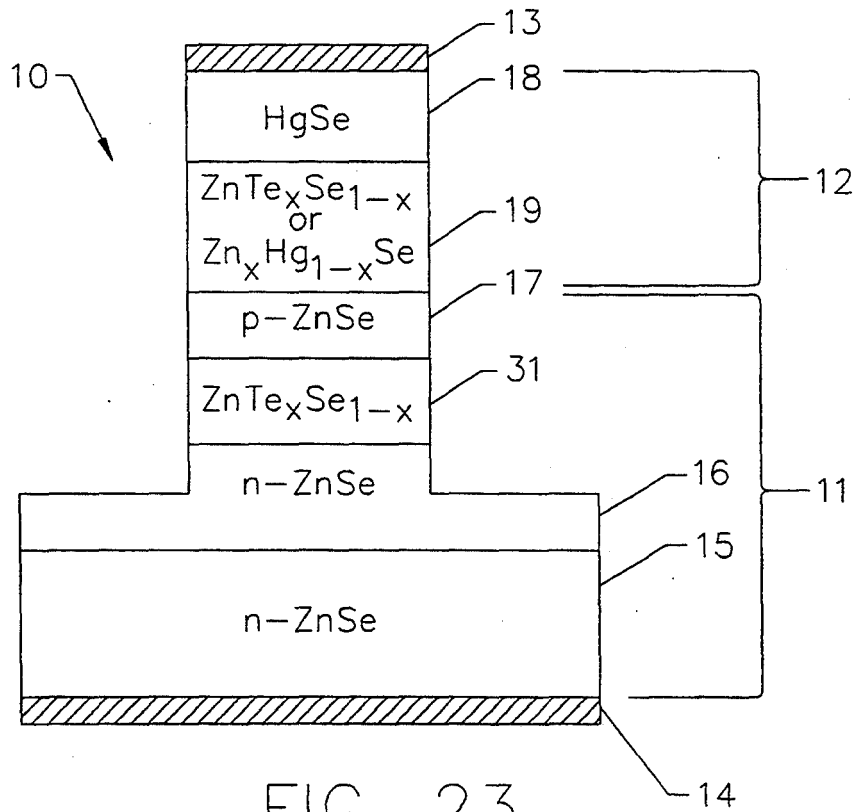


FIG. 23.

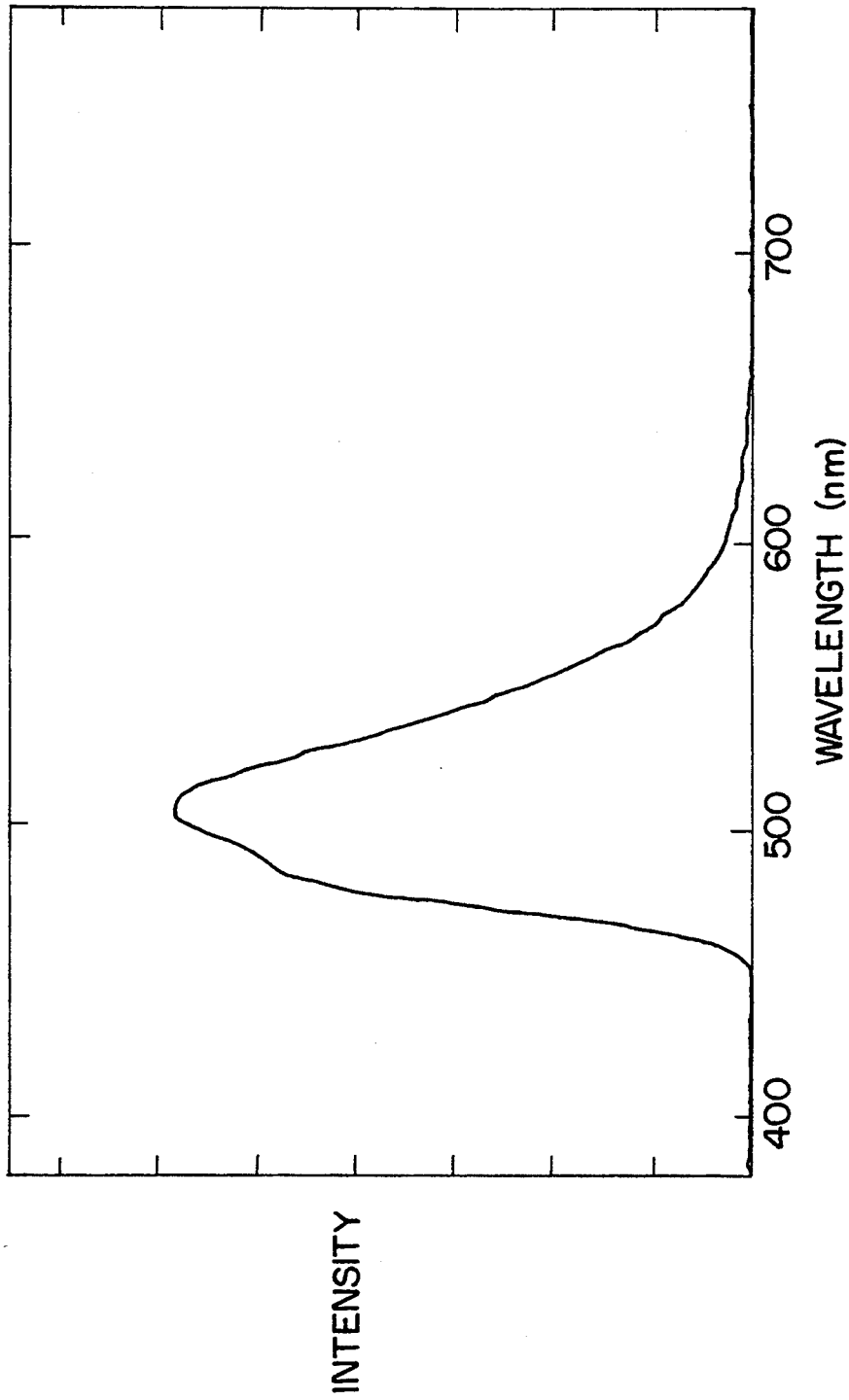


FIG. 24.

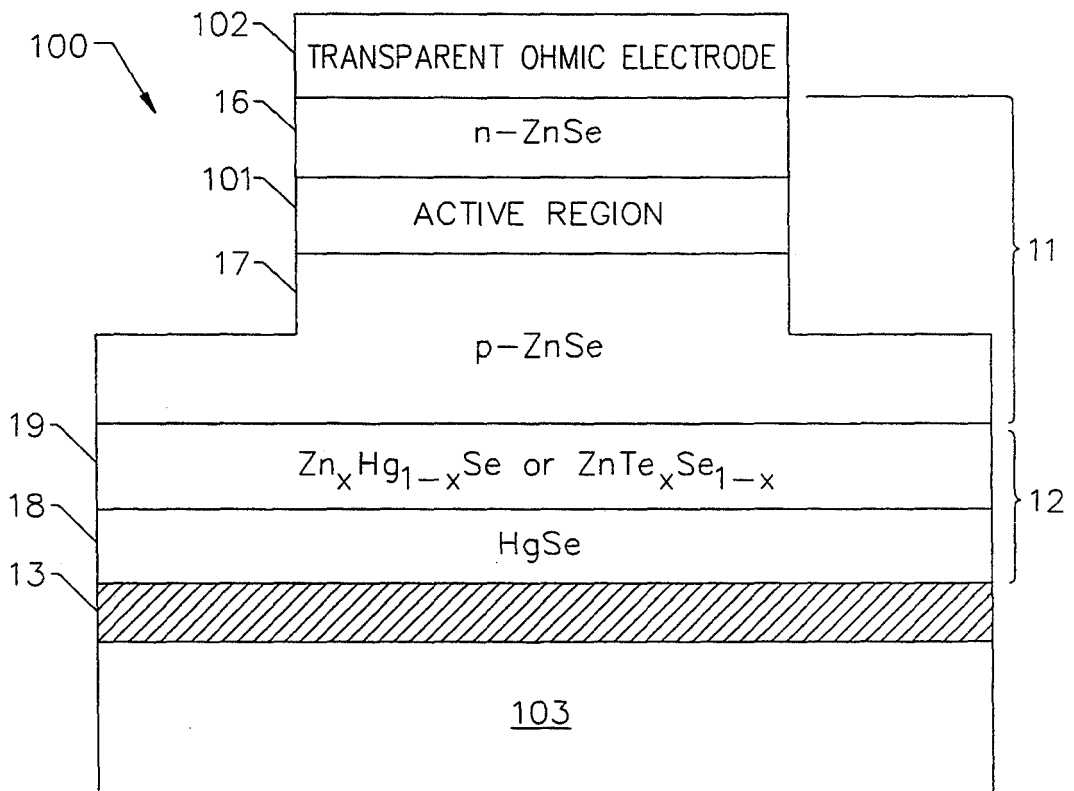


FIG. 25.

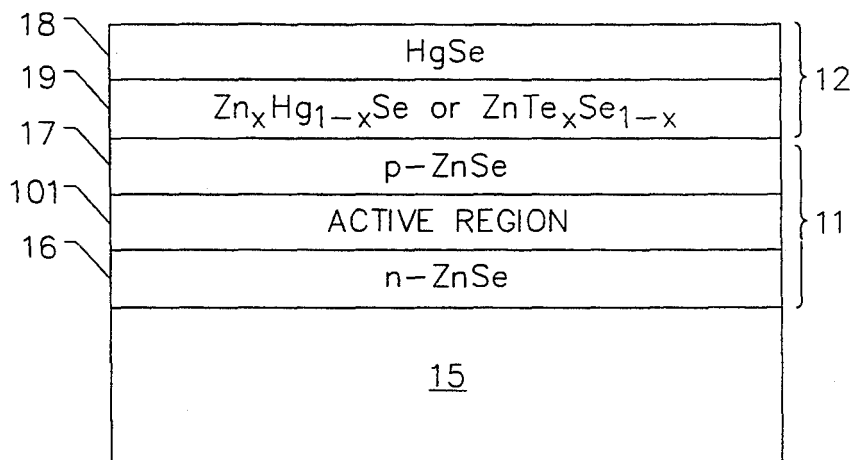


FIG. 26A.

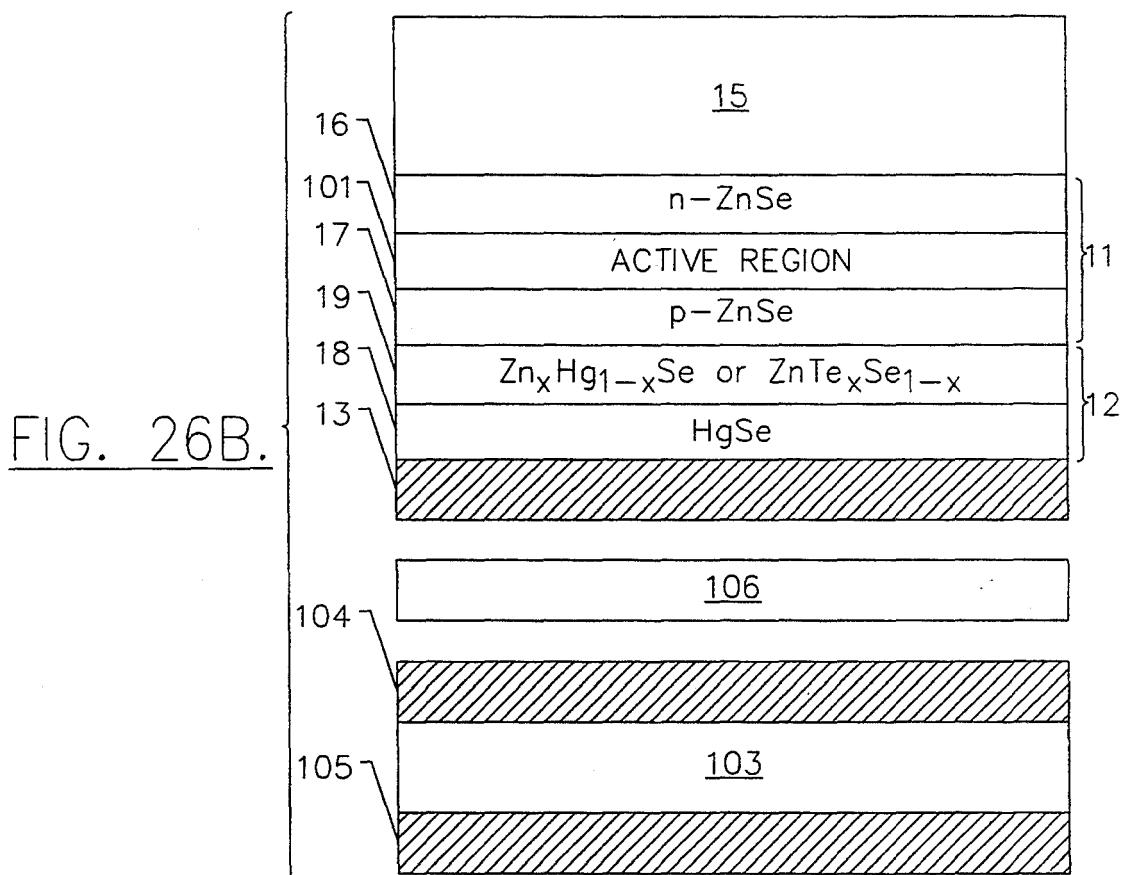


FIG. 26B.

FIG. 26C.

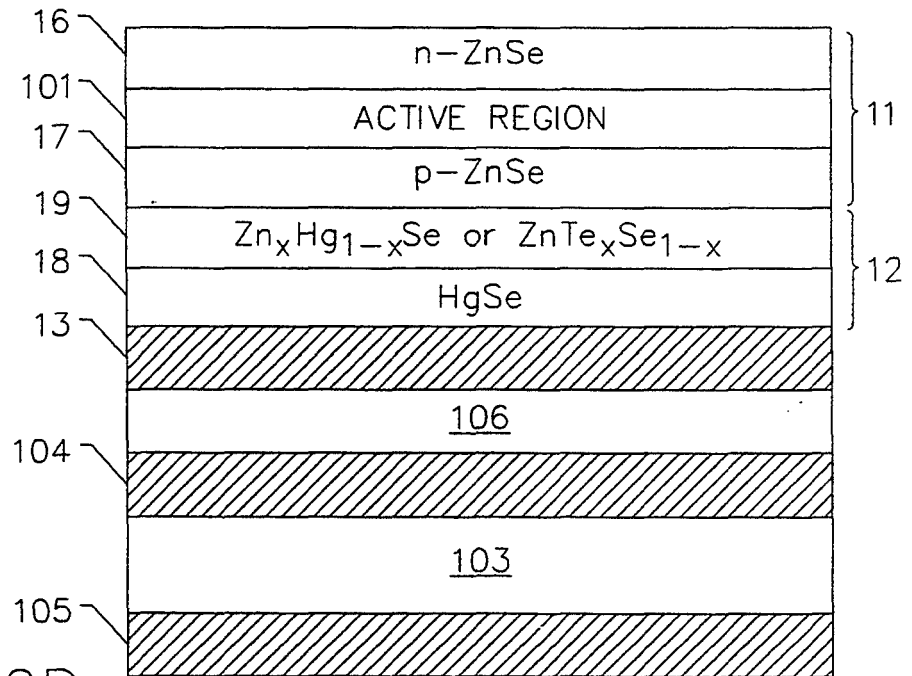
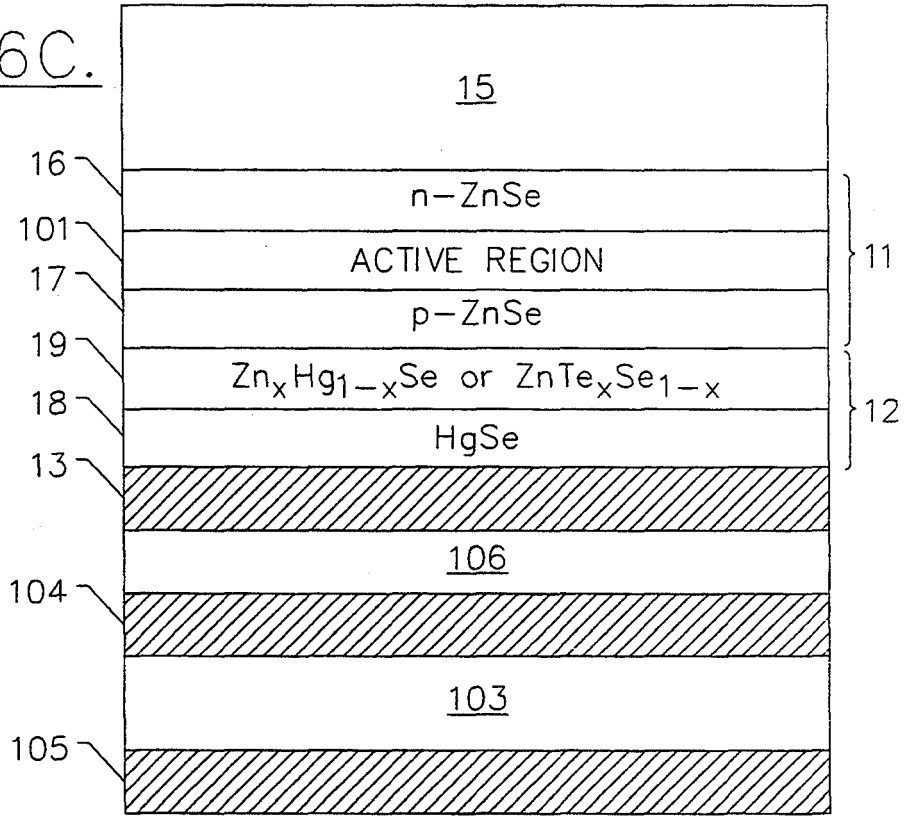


FIG. 26D.

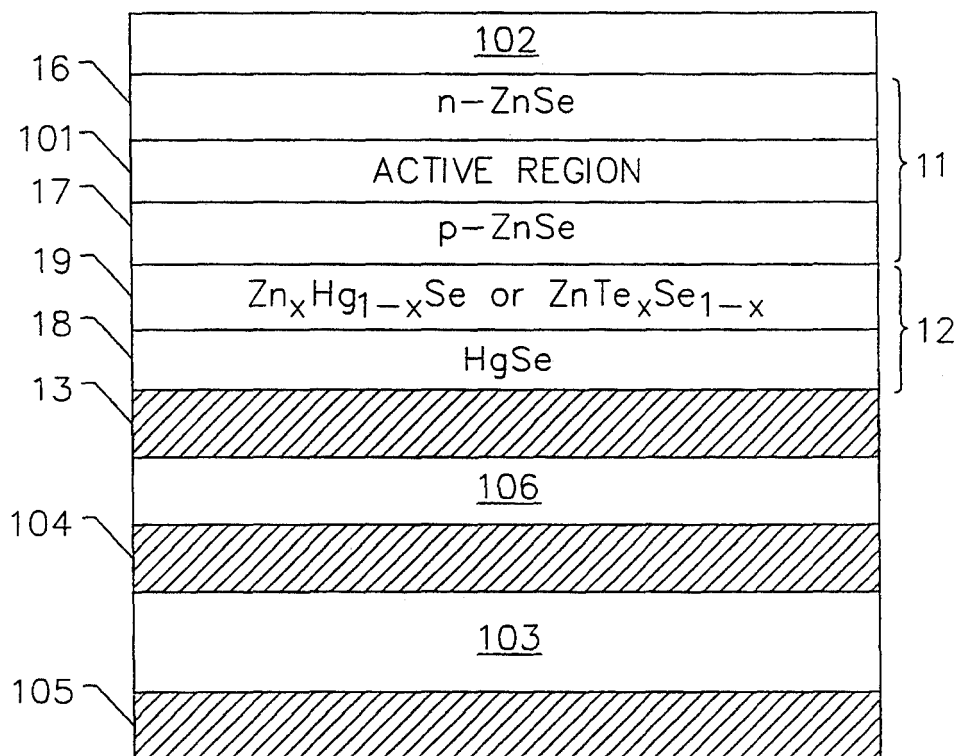


FIG. 26E.

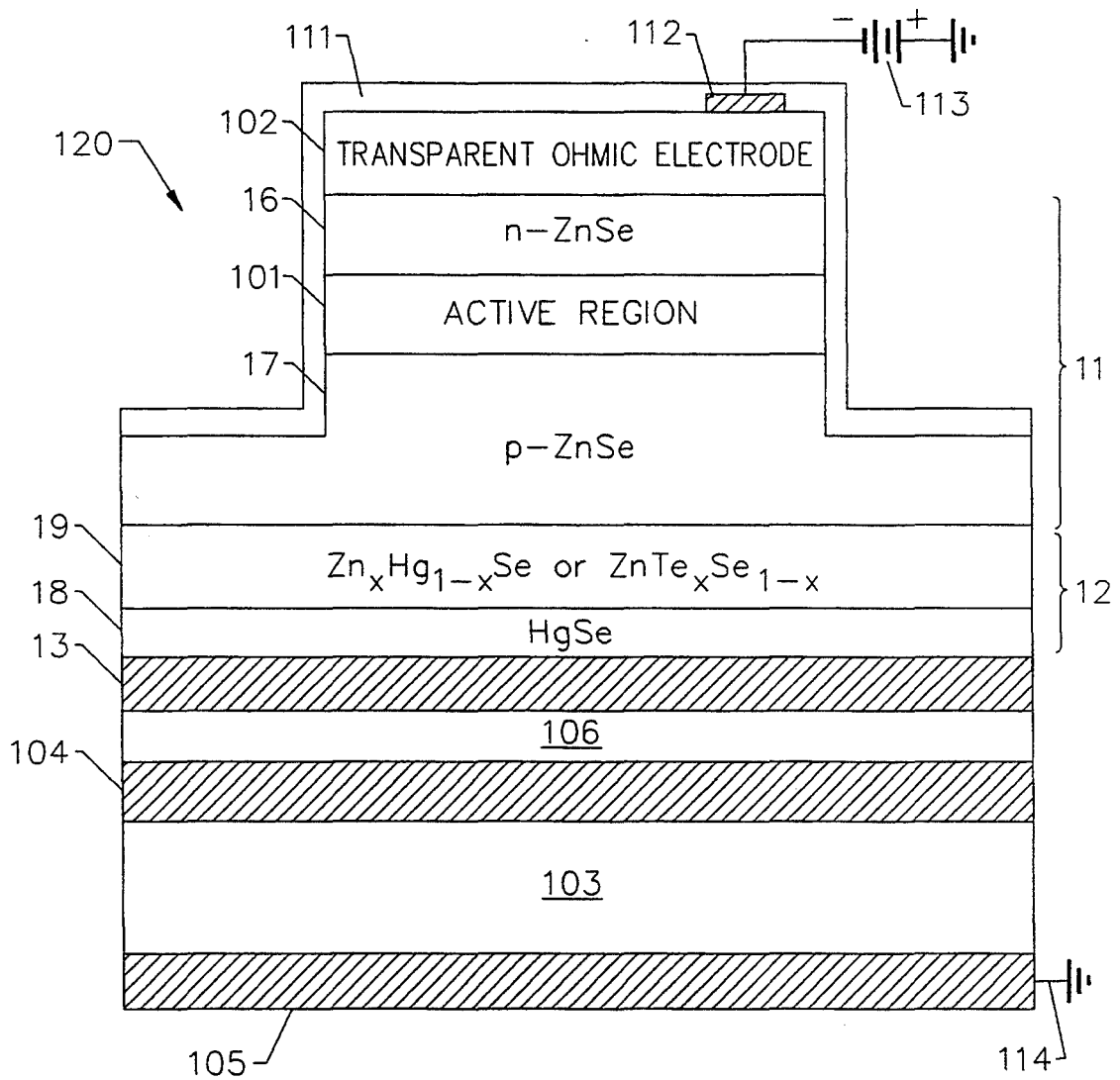


FIG. 27.

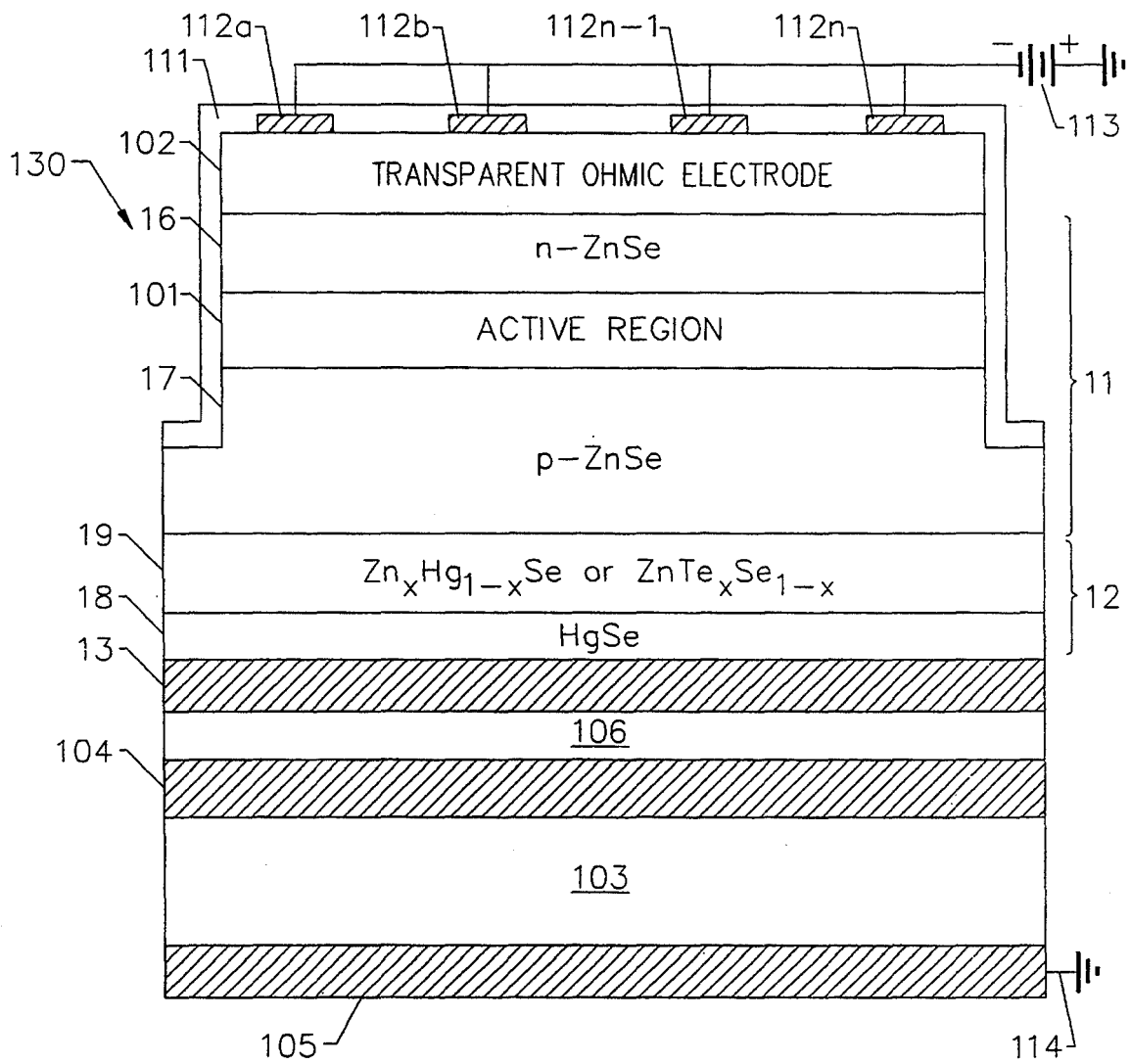


FIG. 28.

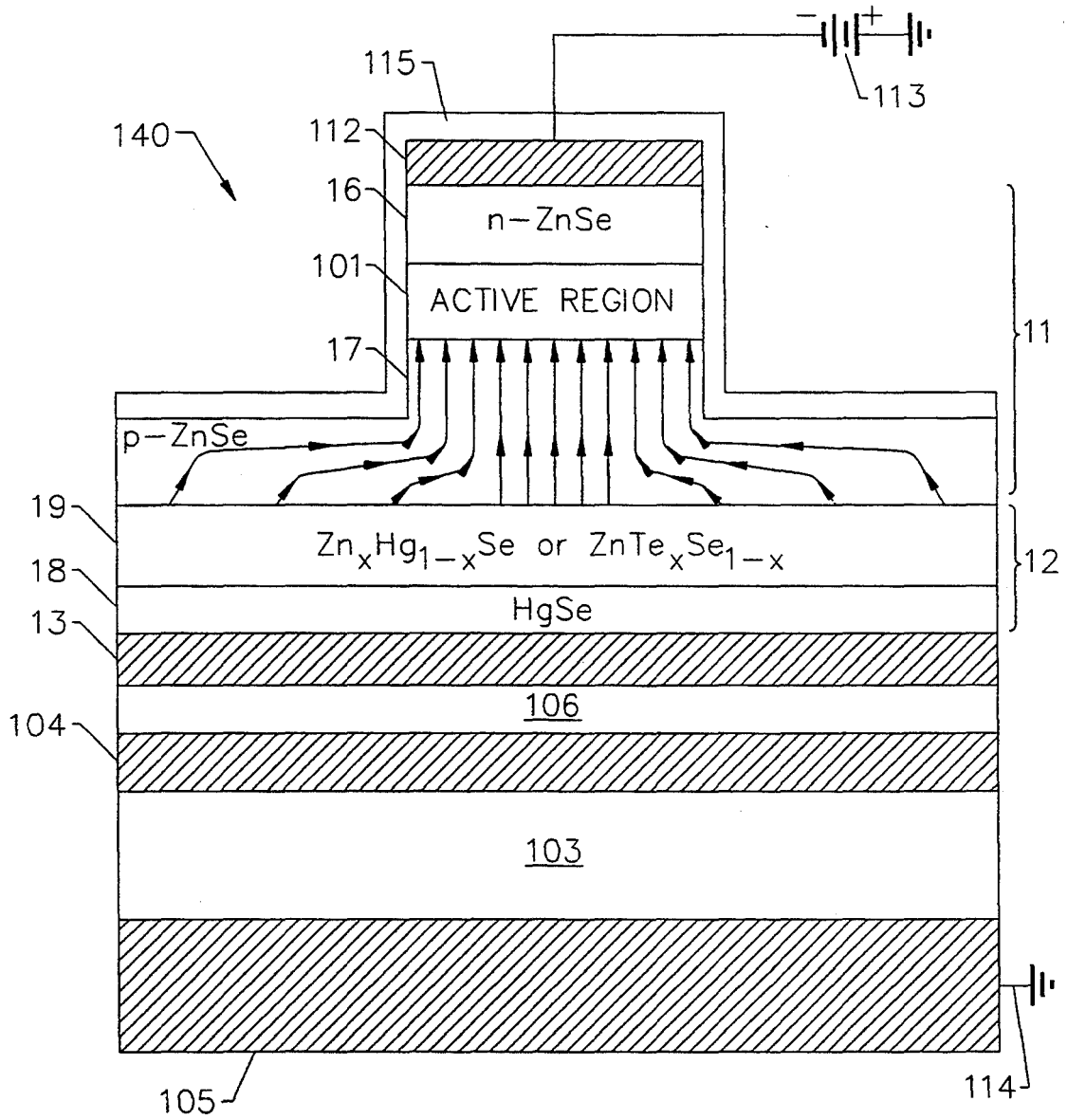


FIG. 29.

INVERTED INTEGRATED HETEROSTRUCTURE OF GROUP II-VI SEMICONDUCTOR MATERIALS INCLUDING EPITAXIAL OHMIC CONTACT AND METHOD OF FABRICATING SAME

U.S. GOVERNMENT RIGHTS

This invention was made with government support under Grant No. DMR-88-13525 awarded by the National Science Foundation. The U.S. Government has certain rights in the invention.

CROSS REFERENCE TO RELATED APPLICATIONS

This application is a continuation-in-part of application Ser. No. 07/934,190 filed Aug. 21, 1992 U.S. Pat. No. 5,294,833, which is itself a continuation-in-part of application Ser. No. 07/881,599 filed May 12, 1992 pending.

FIELD OF THE INVENTION

This invention relates to semiconductor devices, and more particularly to semiconductor devices formed of Group II-VI compound semiconductor materials.

BACKGROUND OF THE INVENTION

Microelectronic applications of Group II-VI semiconductor materials have been widely investigated. In particular, the wide bandgap Group II-VI semiconductor zinc selenide (ZnSe), and its related alloys such as zinc cadmium selenide (ZnCdSe) and zinc sulfur selenide (ZnSSe), are being widely investigated as optoelectronic devices which are effective from the blue to the green region of the visible spectrum. As is well known to those having skill in the art, the wide bandgap of these Group II-VI devices compared to their equivalent nearly lattice matched Group III-V or elemental semiconductor materials, make these wide bandgap Group II-VI semiconductors potential candidates for blue to green optoelectronic devices. Blue to green optoelectronic sources are currently sought for a number of applications, including full color electroluminescent displays, read-write laser sources for high density information storage on magnetic and optical media, sources for undersea optical communications and other applications.

Molecular beam epitaxy and other fabrication techniques have recently been developed so that both n-type and p-type doped layers of zinc selenide and other related II-VI semiconductor materials may be grown. See for example a publication by Ren et al. entitled *Substitutional Doping of ZnSe Films*, Journal of Crystal Growth, Vol. 111, pp. 772-775, 1991. It has also long been known to make Schottky contacts to n-type zinc selenide using mercury selenide (HgSe). See the publications entitled *HgSe, a Highly Electronegative Stable Metallic Contact for Semiconductor Devices* by Best et al., Applied Physics Letters, Vol. 29, No. 7, pp. 433-434, 1976; *Highly Electronegative Contacts to Compound Semiconductors* by Scranton et al., Journal of Vacuum Science and Technology, Vol. 14, No. 4, pp. 930-934, 1977; and *Lattice-Matched Heterostructures as Schottky Barriers: HgSe/CdSe* by Best et al., Journal of Vacuum Science Technology, Vol. 16, No. 5, pp. 1130-1133, 1979.

As a result of these and other developments, at least four research groups have recently described the fabri-

cation of blue and/or green light emitting diodes and/or laser diodes from Group II-VI semiconductors.

The first group is from North Carolina State University (NCSU) and includes the present inventor. The fabrication of blue and green light emitting diodes based on ZnSe and alloys thereof is described in a publication entitled *ZnSe Light-Emitting Diodes* by Ren et al., Applied Physics Letters, Vol. 57, No. 18, pp. 1901-1903, October, 1990, and *Blue (ZnSe) and Green (ZnSe_{0.9}Te_{0.1}) Light Emitting Diodes* by Ren et al., Journal of Crystal Growth, Vol. 111, pp. 829-832, 1991.

A second group of researchers from Brown University and Purdue University have also described zinc selenide based laser diodes and light emitting diodes in publications entitled *Blue-Green Injection Laser Diodes in (Zn, Cd)Se/ZnSe Quantum Wells* by Jeon et al., Applied Physics Letters Vol. 59, No. 27, pp. 3619-3621, December, 1991; *Blue/Green pn Junction Electroluminescence from ZnSe-based Multiple Quantum-Well Structures* by Xie et al., Applied Physics Letters Vol. 60, No. 4, pp. 463-465, January, 1992; *ZnSe Based Multilayer pn Junctions as Efficient Light Emitting Diodes for Display Applications*, Jeon et al., Applied Physics Letters, Vol. 60, No. 7, pp. 892-894, February, 1992; *Blue and Green Diode Lasers in ZnSe-Based Quantum Wells*, Jeon et al., Applied Physics Letters, Vol. 60, No. 17, April, 1992; and *Room Temperature Blue Light Emitting P-N Diodes from Zn(S,Se)-Based Multiple Quantum Well Structures*, Xie et al., Applied Physics Letters, Vol. 60, No. 16, April, 1992, pp. 1999-2001.

A third group from 3M Company described a zinc selenide based laser diode in an article entitled *Blue-Green Laser Diodes* by Haase et al., Applied Physics Letters, Vol. 59, No. 11, pp. 1272-1274, September, 1991. A fourth group from the University of Florida and Bellcore described fabrication of LEDs and light emitting diodes using zinc selenide in an article entitled *Noncontact Electrical Characterization of Low-Resistivity p-type ZnSe:N Grown by Molecular Beam Epitaxy* by Park et al., Applied Physics Letters, Vol. 59, No. 15, pp. 1896-1898, 1991.

The above publications indicate that the art has now successfully fabricated blue and green optoelectrical devices from ZnSe-based materials. As Group II-VI fabrication processes are further refined, optical characteristics such as frequency spectrum width and operational lifetime are expected to improve due to reduced dislocation densities in the materials and other improvements.

A major problem with all of these devices, however, has been the ohmic (nonrectifying) contact to zinc selenide, and in particular to p-type zinc selenide. This is a fundamental problem, which is related to the very deep energy of the valence band of zinc selenide. As a consequence, contacts to p-type zinc selenide and related alloys, using conventional metals such as silver or gold, are not ohmic. In effect, the contacts which have been considered by researchers as being ohmic, actually constitute a reverse biased Schottky diode in series with the device, resulting in a large voltage drop across the supposedly ohmic contact. This large voltage drop results in almost all of the input power to the device being lost as heat. High voltages, of 20-50 V or more, have been required in order to induce optical emission, and the resultant heat destroys the devices.

The "ohmic contact problem" for zinc selenide optical emitter devices has been widely reported. See for example the above cited 1990 Ren et al. article from the

NCSU group, at page 1901: "It was not possible for us to complete Hall effect studies on the ZnSe:Li samples because of problems associated with non-ohmic contacts." See also the above cited 1992 article by Xie et al. from the Brown-Purdue group, at page 463: "Hall measurements on the p-type layers were unreliable due to the difficulty in forming ohmic contacts to the wide-gap semiconductor." See also the Haase et al. article by the 3M group at page 1273: "Heating in these samples is a serious problem as the contact between the Au and the p-ZnSe presents a large barrier." Finally, see the Park et al. article from the University of Florida/Bellcore group which notes that "... serious problems currently exist with regard to providing low-resistance ohmic contact to p-type ZnSe material ..."

The above survey indicates that although significant advances have been made in fabricating Group II-VI devices, and in particular zinc selenide based optoelectronic devices, the ohmic contact to these devices, and in particular to p-type zinc selenide, remains a fundamental concern that has heretofore eluded multiple independent groups of researchers.

SUMMARY OF THE INVENTION

It is therefore an object of the present invention to provide an improved Group II-VI semiconductor device including an ohmic contact therefor.

It is another object of the invention to provide an improved Group II-VI optoelectronic device including an ohmic contact therefor.

It is still another object of the invention to provide an ohmic contact for p-type zinc selenide and alloys thereof.

These and other objects are provided, according to the present invention by an ohmic contact for a semiconductor device formed of Group II-VI semiconductor materials, wherein the contact includes a lattice matched monocrystalline ternary compound Group II-VI semiconductor material on the Group II-VI semiconductor device, a lattice matched monocrystalline Group II-VI semimetal on the Group II-VI semiconductor material and a conductor, such as a metal, on the Group II-VI semimetal. The ternary compound Group II-VI semiconductor material and the semimetal, between the Group II-VI semiconductor material and the conductor layer, eliminate the band offset between the wide bandgap Group II-VI semiconductor material and the conductor layer, to thereby provide an ohmic contact for the Group II-VI semiconductor material.

In particular, according to the invention, an ohmic contact for zinc selenide (ZnSe) or an alloy thereof, and particularly for p-type zinc selenide or an alloy thereof, is provided by a heterostructure including a zinc mercury selenide ($Zn_xHg_{1-x}Se$) layer or a zinc telluride selenide ($ZnTe_xSe_{1-x}$) layer on the layer of zinc selenide or alloy thereof, and a mercury selenide (HgSe) layer on the zinc mercury selenide or zinc telluride selenide layer. A conductor (such as metal) layer is formed on the mercury selenide layer. The zinc mercury selenide or zinc telluride selenide layer, and the mercury selenide layer between the p-type zinc selenide and the conductor layer, provide an ohmic contact by eliminating the band offset between the wide bandgap zinc selenide and the conductor.

Many alternative formulations of the zinc mercury selenide layer and the zinc telluride selenide layer of the present invention may be provided. In particular, the ratio of zinc to mercury, or tellurium to selenium, may

be constant across the layer to provide a step graded zinc mercury selenide layer or zinc telluride selenide layer. Alternatively, the amount of mercury or tellurium may increase from the zinc selenide layer to the mercury selenide layer. One form of increase is a linear increase, to provide a linear graded zinc mercury selenide or zinc telluride selenide layer. Alternatively, and preferably, the amount of mercury or tellurium increases nonlinearly from the zinc selenide layer to the mercury selenide layer to provide a nonlinear graded zinc mercury selenide or zinc telluride selenide layer. Preferably, a parabolic graded layer is provided, in which the amount of mercury or tellurium increases parabolically.

According to the invention, at least some of the zinc mercury selenide layer or zinc telluride selenide layer adjacent the p-type zinc selenide layer is doped p-type. Preferably, half the thickness of the zinc mercury selenide layer or zinc telluride selenide layer, adjacent the zinc selenide layer, is doped p-type, and the other half of the zinc mercury selenide layer or zinc telluride selenide layer, adjacent the mercury selenide layer, is of neutral conductivity. Modulation doping may also be used in the parabolically graded zinc mercury selenide layer or zinc telluride selenide layer.

It has also been found, according to the present invention, that a p-type layer of mercury selenide between the p-type zinc selenide layer and the conductor layer, can provide an ohmic contact for p-type zinc selenide which is far superior to conventional gold or silver ohmic contacts. The ohmic contacts of the present invention produce a nearly ideal (linear) voltage-current relation, indicating that the contacts are indeed ohmic. Hall effect measurements may also be taken, which verify that the contacts are ohmic. When a Group II-VI optoelectronic device is integrated with the ohmic contacts of the present invention, an integrated heterostructure device is formed, with one heterostructure providing an optical function such as e.g. light emission, and another heterostructure providing an electrical function such as ohmic contact. These integrated heterostructures can emit radiation in the blue to green frequency range with an input voltage of five volts or less, resulting in high efficiency Group II-VI optoelectronic devices.

According to another aspect of the present invention, in certain applications it is desirable to provide large area optical emitters such as light emitting diodes (LED), in which the light is emitted from the top and sides of the LED. Such large area LEDs can be used to produce numerical display arrays and many other devices. According to the invention, the integrated heterostructures of the present invention may be used to produce large area optical emitters by providing a mercury selenide layer, or a mercury selenide layer on the zinc mercury selenide or zinc telluride selenide layer, which is sufficiently thick to provide an ohmic contact to the p-type zinc selenide layer, and is sufficiently thin to pass optical emissions from the optical emission heterostructure therethrough. Preferably, a mercury selenide layer less than about 100 Å thick, is provided. Although mercury selenide is a semimetal which absorbs radiation through the visible and infrared spectral regions, the thin mercury selenide layer is thin enough to limit the light absorption losses to less than 10%. Moreover, since mercury selenide is of very high conductivity, the mercury selenide layer is sufficiently thick to act as a semitransparent electrode which covers

the top of the heterostructure. In order to further reduce the surface contact resistance, a transparent conductor layer such as indium tin oxide may be formed on the thin layer of mercury selenide.

An integrated heterostructure according to the present invention may be formed by epitaxially forming an optical heterostructure and an electrical heterostructure as described above. Typically, the optical heterostructure (such as a laser diode or light emitting diode) is formed in a first chamber, using molecular beam epitaxy (MBE) of zinc selenide and related alloys. The zinc mercury selenide electrical heterostructure (ohmic contact) is typically fabricated in a second deposition chamber because of the special requirements for depositing mercury based materials. Transfer between the first and second chambers typically must take place under ultra high vacuum conditions.

Alternatively, according to the present invention, a mercury based electrical heterostructure may be formed on a zinc selenide based optical heterostructure without the need for ultra high vacuum transfer between MBE chambers, by forming a thin overcoat layer, for example, selenium, on the optical heterostructure. This structure can then be removed from the zinc selenide MBE chamber and inserted into a mercury based MBE chamber at room temperature and under atmospheric conditions. Once the structure is placed in the mercury based chamber, and the chamber is evacuated, the selenium overcoat layer may be evaporated and the mercury based electrical heterostructure may be epitaxially formed on the zinc selenide based optical heterostructure.

Similarly, in order to prepare the integrated heterostructure of the present invention which includes a zinc telluride selenide layer, the optical heterostructure (such as a laser diode or light emitting diode) is formed in a first chamber, using molecular beam epitaxy (MBE) of zinc selenide and related alloys. The zinc telluride selenide layer of the electrical heterostructure (ohmic contact) is also fabricated in the first deposition chamber, for example by continuing molecular beam epitaxy growth at about 250° C. Growth of a graded zinc telluride selenide layer may be accomplished by decreasing the temperature of the selenium MBE source oven, preferably under computer control, while increasing the source temperature of the tellurium MBE source oven. An optional thin layer (about 100 Å) of p-type zinc telluride may be formed on the graded layer of zinc telluride selenide.

Following deposition of the zinc telluride selenide graded layer, a thin overcoat layer, for example selenium, is formed. The structure can then be removed from the first MBE chamber and inserted into a second, mercury based MBE chamber at room temperature and under atmospheric conditions. Once the structure is placed in the mercury based chamber, and the chamber is evacuated, the selenium overcoat layer may be evaporated, and a layer of mercury selenide may be deposited at about 100° C. in the second MBE chamber. Accordingly, the zinc telluride selenide layer can be grown in a first MBE chamber using the same low growth temperature (about 250° C.) as the optical heterostructure of the integrated heterostructure device. The graded layer can be doped p-type using nitrogen from the same remote plasma source that is used to prepare the p-type layers of the optical portion of the integrated heterostructure device. Accordingly, growth of the layer of zinc telluride selenide is simpler than the growth of the

zinc mercury selenide layer of Application Serial No. 07/881,599.

According to yet another aspect of the present invention, a high efficiency blue/green optical emitter is formed using a layer of the quaternary alloy zinc sulfur telluride selenide ($ZnS_xTe_ySe_z$, where $x+y+z=1$) between two layers of zinc sulfur selenide ($ZnSSe$), or a layer of the ternary compound zinc telluride selenide ($ZnTe_xSe_{1-x}$) between layers of zinc selenide ($ZnSe$). The zinc sulfur telluride selenide or zinc telluride selenide layers form a quantum well, and multiple layers may be used to form multiple quantum wells. In an LED application, a layer about 1000 Å thick will typically be formed while in a laser, a layer about 100–200 Å thick will be formed. Tellurium forms an isoelectronic trap which produces broad and intense light output in the blue/green spectral region.

The cladged zinc sulfur telluride selenide or zinc telluride selenide structure is preferably formed on a substrate such as gallium arsenide or zinc selenide. Zinc sulfur selenide and zinc sulfur telluride selenide are used with gallium selenide substrates because of their close lattice match thereto. For zinc selenide substrates, zinc selenide and zinc telluride selenide are used. A mercury selenide, zinc mercury selenide or zinc telluride selenide layer is used to form an ohmic contact to the zinc selenide or zinc sulfur selenide. The emitters are relatively easy to fabricate because no adjustments need be made to the zinc, sulfur, tellurium or selenium fluxes. Rather, these fluxes need only be turned on and off at the appropriate time during deposition to form the structure.

According to another aspect of the present invention, an inverted integrated heterostructure of Group II-VI semiconductor materials including an epitaxial ohmic contact is provided. The inverted heterostructure includes a transparent ohmic electrode on the n-type zinc selenide layer, rather than on the p-type zinc selenide layer as already described. Thus, optical emissions occur from the active region of the optical emissions heterostructure through the n-type zinc selenide layer and the transparent ohmic electrode, rather than from the active region to the p-type zinc selenide layer and the epitaxial ohmic contact including a layer of mercury selenide, as was already described.

In particular, an inverted integrated heterostructure according to the present invention includes an optical emission heterostructure formed of Group II-VI compound semiconductor materials, having first and second opposing faces, and including a layer of p-type zinc selenide or an alloy thereof at the first face. A zinc mercury selenide or zinc telluride selenide layer is formed on the layer of p-type zinc selenide or an alloy thereof, and a mercury selenide layer is formed on the zinc mercury selenide or zinc telluride selenide layer, opposite the optical emission heterostructure. An ohmic electrode is formed on the mercury selenide layer opposite the zinc mercury selenide or zinc telluride selenide layer, and a transparent ohmic electrode is formed on the second face of the optical emission heterostructure for allowing optical emissions from the optical emission heterostructure to pass therethrough. Thus, the structure is inverted from that already described, with the optical emission occurring through the n-type zinc selenide layer, rather than through the epitaxial ohmic contact including the mercury selenide layer.

The ohmic electrode is preferably an optically reflecting ohmic electrode, for reflecting optical emissions from the optical emission heterostructure back

into the optical emission heterostructure, so that these emissions exit through the n-type zinc selenide layer and the transparent ohmic electrode. Also preferably, a substrate is included on the ohmic electrode opposite the mercury selenide layer. The substrate is preferably an electrically conducting substrate and includes a second ohmic metal layer electrode thereon. An electrically conducting bonding layer bonds the first ohmic metal electrode and the second ohmic metal electrode. The substrate is most preferably an electrically and thermally conducting substrate which may be a thick metal substrate or a heavily doped semiconductor substrate or combinations thereof.

A method of forming an inverted integrated heterostructure according to the present invention begins by first forming an optical emission heterostructure including an epitaxial ohmic contact on a first substrate as already described. In particular, the optical emission heterostructure includes a layer of p-type zinc selenide or an alloy thereof opposite the first substrate, a zinc mercury selenide layer or a zinc telluride selenide layer on the layer of p-type zinc selenide or an alloy thereof, and a mercury selenide layer on the zinc mercury selenide or zinc telluride selenide layer, opposite the optical emission heterostructure. The mercury selenide layer is then bonded to a second substrate and the first substrate is removed.

The bonding step may be accomplished by forming a first ohmic metal electrode on the mercury selenide layer, opposite the optical emission heterostructure, forming a second ohmic metal electrode on the second substrate, and bonding the first and second ohmic metal electrodes to one another. The first substrate is then removed. Bonding may take place using solder, conductive epoxy or other known bonding means. After the first substrate is removed, a transparent ohmic electrode is formed on the optical emission heterostructure opposite the layer of p-type zinc selenide or an alloy thereof.

The present invention forms an n-on-p structure which is a high efficiency optical emitter because a simple transparent ohmic electrode can be used at the top contact to the n-type zinc selenide, and because a metal reflecting contact can be formed under the mercury selenide layer. Moreover, since the first substrate is removed, heteroepitaxy induced defects associated with lattice mismatch between the first substrate and the n-type zinc selenide layer are eliminated. These heteroepitaxy induced defects are one of the major causes of dark-line and other defects that limit the lifetime of Group II-VI optical emission heterostructures. Finally, the second substrate which is bonded to the optical emission heterostructure may provide heat sinking for removing heat generated in the epitaxial ohmic contact and the optical emission heterostructure, thus improving the power handling capability of the device. High efficiency, long life, optical emission heterostructures of Group II-VI semiconductor materials are thereby provided.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is a cross-sectional illustration of a first embodiment of an optical emitter having an ohmic contact according to the present invention.

FIG. 2 graphically illustrates energy bandgap versus lattice constant for selected semiconductor materials.

FIG. 3 is an energy band diagram illustrating the band offsets between zinc selenide and gallium arsenide.

FIG. 4 is an energy band diagram showing the energy band lineup between gold and zinc selenide.

FIG. 5 is an energy band diagram illustrating the band lineups of a zinc selenide p-on-n diode under forward bias.

FIG. 6 graphically illustrates the current-voltage characteristics of various zinc selenide based heterostructures.

FIG. 7 is an energy band diagram showing the band lineup between cadmium telluride and mercury telluride.

FIG. 8 is an energy band diagram showing the band lineups between zinc selenide and mercury selenide.

FIG. 9 is a graphical illustration of the voltage current relationship for an ohmic contact according to the present invention.

FIG. 10a illustrates the current-voltage relationship for a known zinc selenide light emitting diode.

FIGS. 10b-10d illustrate the current-voltage relationships for light emitting diodes including an ohmic contact according to the present invention.

FIG. 11 is a graphical illustration of the current-voltage relationship among known light emitting diodes and light emitting diodes fabricated according to the present invention.

FIG. 12 is a cross-sectional illustration of a second embodiment of the present invention.

FIG. 13 is an energy band diagram for the device shown in FIG. 12, including a step graded zinc mercury selenide layer.

FIG. 14 is an energy band diagram for the device shown in FIG. 12, including a linear graded zinc mercury selenide layer.

FIG. 15 is an energy band diagram for the device shown in FIG. 12, including a parabolic graded zinc mercury selenide layer.

FIGS. 16a-16p are cross-sectional illustrations of alternative combinations of integrated heterostructures according to the present invention.

FIG. 17 illustrates another integrated heterostructure according to the present invention.

FIGS. 18a and 18b illustrate steps for forming the integrated heterostructure of FIG. 17 according to the present invention.

FIGS. 19a and 19b illustrate alternative steps for forming the integrated heterostructure of FIG. 17 according to the present invention.

FIG. 20 graphically illustrates the current-voltage relationship for a light emitting diode which does not include an ohmic contact according to the present invention.

FIG. 21 graphically illustrates the current-voltage relationship for a light emitting diode which includes an ohmic contact according to the present invention.

FIGS. 22 and 23 are cross-sectional illustrations of alternative integrated heterostructures according to the present invention.

FIG. 24 graphically illustrates wavelength versus intensity for the structure of FIG. 22.

FIG. 25 is a cross-sectional illustration of an inverted integrated heterostructure device according to the present invention.

FIGS. 26A-26E illustrate the structure of FIG. 25 during intermediate fabrication steps.

FIG. 27 is a cross-sectional illustration of a first embodiment of a light emitting diode according to the present invention.

FIG. 28 is a cross-sectional illustration of a second embodiment of a light emitting diode according to the present invention.

FIG. 29 is a cross-sectional illustration of a laser diode according to the present invention.

DESCRIPTION OF A PREFERRED EMBODIMENT

The present invention now will be described more fully hereinafter with reference to the accompanying drawings, in which a preferred embodiment of the invention is shown. This invention may, however, be embodied in many different forms and should not be construed as limited to the embodiment set forth herein; rather, this embodiment is provided so that this disclosure will be thorough and complete, and will fully convey the scope of the invention to those skilled in the art. Like numbers refer to like elements throughout.

Referring now to FIG. 1, a first embodiment of an optical emitter having an ohmic contact according to the present invention is illustrated. Optical emitter 10 is an integrated heterostructure including an optical heterostructure 11 and an electrical heterostructure 12. Optical heterostructure 11 can be a well known blue to green light emitting diode or laser diode structure, or any other Group II-VI device now known or discovered later. As shown in FIG. 1, the optical heterostructure 11 is a blue light emitting diode (LED). The blue LED is formed on a substrate 15 of zinc selenide, gallium arsenide or any other known material. The LED is a p-n junction between n-type zinc selenide layer 16 and p-type zinc selenide layer 17. Both zinc selenide layers may be formed on substrate 15 using well known techniques such as molecular beam epitaxy, and both layers may be doped at 10^{18} carrier per cubic centimeter. Bottom contact 14 is formed of metal such as gold-germanium for n-type GaAs or indium for n-type ZnSe, or other well known conductors. It will be understood by those having skill in the art, that, as used herein, when a layer is formed "on" another layer, it may be formed directly on the underlying layer, or one or more intervening layers may be present.

Still referring to FIG. 1, the electrical portion 12 of the integrated heterostructure 10 comprises a layer of mercury selenide. As is well known to those having skill in the art, mercury selenide is a semimetal rather than a semiconductor, because it has a bandgap that is zero. It will be understood by those having skill in the art that the integrated optical structure 11 and electrical structure 12 is epitaxially formed as a monolithic structure, with lattice match between adjacent layers so as to produce minimal dislocations at the junctions between the layers. FIG. 2 illustrates the energy bandgap versus lattice constant for various Group IV single element semiconductors, Group III-VI compound semiconductors and Group II-VI compound semiconductors and semimetals.

It has been found, according to the invention, that mercury selenide forms a good ohmic contact to p-type zinc selenide and thereby solves the last fundamental problem in development of high efficiency Group II-VI devices. FIG. 3 illustrates the origin of the ohmic contact problem. As shown in FIG. 3, there is essentially no conduction band (E_c) offset between zinc selenide and gallium arsenide. As a consequence, valence band (E_v) offset is very large: about 1.3 electron volts (eV). The deep valence band of zinc selenide is the source of the ohmic contact problem. Gold, which has

the largest work function of all metals, has proven to be an ineffective ohmic contact to zinc selenide. Gold forms a barrier of about 1.1 electron volts on n-type zinc selenide. A gold/zinc selenide interface, as shown in FIG. 4, produces a band offset of about 1.6 electron volts. Accordingly, the use of gold as an ohmic contact to a p-on-n zinc selenide homojunction, produces the band bending shown in FIG. 5.

Under forward bias of the zinc selenide diode, the gold/p-type zinc selenide junction is reverse biased and current flow is limited by carrier tunneling through the heterobarrier. This is illustrated by the current-voltage characteristics shown in FIG. 6 as reported by the 3M Group for their initial laser diode. Data for LED's prepared by the NCSU group is also shown to illustrate that the forward characteristics are similar for samples prepared in different laboratories. This data strongly suggests that the current limiting device is a series diode undergoing reverse breakdown. This diode is associated with reverse breakdown via carrier tunneling of the gold-zinc selenide Schottky diode heterointerface.

In order to develop high efficiency LEDs and lasers from zinc selenide and related materials, the ohmic contact problem must be solved. A solution to the ohmic contact problem has been found by studying the valence band offset between mercury telluride (HgTe) and cadmium telluride (CdTe). As shown in FIG. 7, it has been found that the valence band offset is 0.35 electron volts. Earlier estimates, based on the "common anion rule" implied a band offset of zero. Accordingly, the common anion rule must be rephrased as a "modified common anion rule" for Group II-VI materials containing mercury which is consistent with the mercury telluride/cadmium telluride valence band offset results. As shown in FIG. 7, a modified common anion rule gives:

$$\Delta E_c/\Delta E_v = 1.25/0.350 = 3.6 \quad (1)$$

If Equation (1) holds for the mercury selenide/zinc selenide interface, then

$$\Delta E_c + \Delta E_v = E_q(\text{ZnSe}) = 2.70 \text{ eV} \quad (2)$$

and a valence band offset ΔE_v of 0.59 electron volts is obtained for the mercury selenide/zinc selenide interface as shown in FIG. 8. This represents nearly a three-fold decrease compared to a gold/zinc selenide interface barrier of about 1.6 electron volts. Thus, a layer of epitaxial mercury selenide on p-type zinc selenide should provide a much better ohmic contact than gold.

FIG. 9 graphically illustrates the voltage-current relationship for an ohmic contact according to the present invention. In order to fabricate this ohmic contact, a layer of mercury selenide was grown, by molecular beam epitaxy, onto p-type (nitrogen doped) zinc selenide samples. Standard photolithographic processing was then used to define four contacts on each of the samples for Hall effect measurements. FIG. 9 shows the current-voltage relationship between adjacent Hall contacts one centimeter apart of a representative sample. Apart from a small (about 0.1 volt) offset, the contacts are very nearly ohmic, thus indicating that electrical contacts, good enough for Hall effect measurement, are now available.

Several diode structures were prepared using molecular beam epitaxy deposition. The p-type layers included zinc sulfur selenide doped with nitrogen fol-

lowed by a layer of nitrogen doped p-type zinc selenide and a layer of mercury selenide. Diodes were then prepared for testing using standard techniques.

FIG. 10a illustrates the current-voltage relationship of an earlier device which used lithium as the p-type dopant and gold as the electrical contact to the p-type zinc selenide layer. As shown, about 10 V is required to obtain 1 mA current under forward bias conditions for a diode having a cross-sectional area of 10^{-3} cm². FIGS. 10b-10d illustrate diodes including zinc selenide and mercury selenide layers, according to the present invention. As shown, these diodes of cross-sectional area 10^{-3} cm² turn on at a much lower voltage (2.1 V to obtain 1 mA, 3.2 V to obtain 10 mA and 4.4 V to obtain 50 mA as shown in FIGS. 10b-10d, respectively). This dramatic increase in current at a given voltage compared with earlier diodes provides clear evidence that the ohmic contact of the present invention is effective.

FIG. 11 graphically compares the diodes fabricated according to the present invention as described above ("NCSU p-on-n diodes 2/92") with those produced by 3M and Purdue. As shown, the p-on-n diodes of the present invention are substantially improved from those reported by 3M. Indeed, the diodes of the present invention are substantially better than the Purdue results for n-on-p diodes, particularly when diodes of similar cross-sectional areas are compared.

Referring now to FIG. 12, a second integrated heterostructure 20 is shown which includes a further improved ohmic contact from that of FIG. 1. As shown in FIG. 12, the optical heterostructure 11 is identical to that of FIG. 1. However, the electrical heterostructure comprises a layer of zinc mercury selenide ($Zn_xHg_{1-x}Se$) 19 or zinc telluride selenide ($ZnTe_xSe_{1-x}$) between the layer of mercury selenide 18 and the p-type zinc selenide layer 17. The layer of mercury selenide 18 and the layer of zinc mercury selenide or zinc telluride selenide 19 provide an improved ohmic contact between p-type zinc selenide layer 17 and conductor 13.

According to the invention, alternative embodiments of zinc mercury selenide layer or zinc telluride selenide layer 19 can provide an ohmic contact. In one embodiment, zinc mercury selenide layer or zinc telluride selenide layer 19 is a step graded layer having uniform ratio of zinc to mercury or tellurium to selenium respectively, across the entire thickness thereof. A preferred uniform ratio for this layer is about 1:1. FIG. 13 illustrates the energy band diagram for such a step graded zinc mercury selenide layer. Preferably the step graded layer of zinc mercury selenide or zinc telluride selenide is doped p-type with the same doping concentration (10^{18}) as the zinc selenide layer. Nitrogen doping is preferred.

Another alternative is shown in FIG. 14 wherein the amount of mercury or tellurium increases linearly across the zinc mercury selenide or zinc telluride selenide layer respectively, from the zinc selenide layer to the mercury selenide layer, to thereby provide a linear graded zinc mercury selenide or zinc telluride selenide layer. Preferably, the linear graded layer of zinc mercury selenide or zinc telluride selenide is doped p-type with the same doping concentration as the p-type zinc selenide (e.g. 10^{18}).

Referring now to FIG. 15, the most preferred embodiment presently contemplated by the inventor, is a parabolic graded zinc mercury selenide or zinc telluride selenide layer. As further shown in FIG. 15, at least part of the zinc mercury selenide layer or zinc telluride sele-

nide layer is doped p-type, and preferably a portion of the zinc mercury selenide layer or zinc telluride selenide adjacent the zinc selenide layer is doped p-type. Most preferred is a configuration wherein half the thickness of the zinc mercury selenide layer or zinc telluride selenide layer adjacent the zinc selenide layer is doped p-type, with the same doping concentration as the zinc selenide, and with half the layer adjacent the mercury selenide being undoped. In one configuration, the zinc mercury selenide layer or zinc telluride selenide layer is 1200 Å thick, with 600 Å adjacent the zinc selenide layer being doped p-type (preferably with nitrogen) at 10^{18} carriers per cubic centimeter to match that of the p-type zinc selenide, and with 600 Å adjacent the mercury selenide being undoped. An optional thin (about 100 Å) layer of p-type zinc telluride (ZnTe) may be formed on the graded zinc telluride selenide layer, to ensure that the interface with the mercury selenide layer is pure ZnTe.

It will be understood by those having skill in the art that in display and other applications it is desirable to provide broad area optical emitters which preferably emit light from the entire top and sides of the emitter. According to the invention, the thickness of mercury selenide layer 18 is limited so that the mercury selenide layer acts as a semitransparent electrode, with a substantial portion of the light emitted from the optical emitter passing through the layer of mercury selenide 18. Preferably, the layer of mercury selenide is less than about 100 Å thick. In this case, although mercury selenide is a semimetal which absorbs throughout the visible and infrared spectral regions, the mercury selenide layer is thin enough so that the light absorption losses are less than about 10%. In addition, the very high conductivity of the mercury selenide layer allows it to act as a semitransparent electrode which covers the entire top of the optical structure. Blue light emitting diodes which emit light at 476 nm over a large surface area with a room temperature efficiency of greater than 0.02% may be obtained using operational voltages of only 4.5 volts to produce 50 mA through the integrated heterostructure.

In order to further reduce the resistance of the large area emitter, conductor 13 may be formed of indium tin oxide, a well known transparent electrode material. The use of indium tin oxide conductor 13 in combination with a mercury selenide layer 18, less than 100 Å thick, enhances the current spreading at the top of the emitter so that numerals or other symbols approaching 1 cm by 1 cm in surface area can be fabricated.

It will also be understood by those having skill in the art that any of the ohmic contacts 12 of the present invention may be combined with any Group II-VI devices to form an integrated heterostructure device. FIGS. 16a-16p illustrate various constructions.

FIGS. 16a-16d illustrate green LEDs. In particular, FIG. 16a illustrates a mesa diode green LED including a ZnCdSe quantum well 31. FIG. 16b illustrates a multiple quantum well (MQW) mesa diode green LED including an MQW 32 of ZnSe and ZnCdSe. FIG. 16c illustrates a Graded Index Separate Confinement Heterostructure ("GRINSCH") mesa diode green LED including a layer of graded p-type ZnCdSe a ZnCdSe quantum well 34 and graded n-type ZnCdSe FIG. 16d illustrates a GRINSCH-MQW mesa diode green LED including a graded layer of p-type ZnCdSe 36 and a layer of ZnCdSe 37, and a graded layer of n-type ZnCdSe 38.

FIGS. 16e-16h illustrate blue LEDs. FIG. 16e illustrates a mesa diode blue LED including p- and n-type layers of zinc sulfur selenide and a zinc cadmium selenide quantum well 41. FIG. 16f illustrates an MQW mesa diode blue LED including an MQW 42 of zinc sulfur selenide and zinc cadmium selenide. FIG. 16g illustrates a GRINSCH mesa diode blue LED including a layer graded p-type zinc sulfur selenide layer 43, a zinc cadmium selenide quantum well 44 and a graded n-type zinc sulfur selenide layer 45. FIG. 16h illustrates a GRINSCH MQW blue LED including a graded layer of p-type zinc sulfur selenide 46, an MQW of zinc sulfur selenide and zinc cadmium selenide 47, and a graded layer of n-type zinc sulfur selenide 48.

FIGS. 16i-16l illustrate green lasers. FIG. 15i illustrates a GRINSCH green laser, including a graded layer of p-type zinc cadmium selenide 51, a zinc cadmium selenide quantum well 52, and a graded layer of n-type zinc cadmium selenide 53. FIG. 16j illustrates a separate confinement green laser formed by a layer of p-type zinc cadmium selenide 54, a zinc cadmium selenide quantum well 56 and an n-type zinc cadmium selenide layer 57. FIG. 16k illustrates a GRINSCH MQW green laser including a graded layer of p-type zinc cadmium selenide 58, a zinc cadmium selenide MQW 59 and a graded layer of n-type zinc cadmium selenide 61. A separate confinement MQW green laser is shown in FIG. 16l including a p-type layer of zinc cadmium selenide 62, a zinc cadmium selenide MQW 63 and n-type zinc cadmium selenide layer 64.

FIGS. 16m-16p illustrate blue lasers. In particular, FIG. 16m illustrates a GRINSCH MQW blue laser formed of graded p-type zinc sulfur selenide layer 66, an MQW 67 of zinc sulfur selenide and zinc cadmium selenide, and a graded layer of n-type zinc sulfur selenide 68. FIG. 16n illustrates a GRINSCH blue laser including graded p-type zinc sulfur selenide layer 71, a zinc cadmium selenide layer quantum well 72 and a graded n-type zinc sulfur selenide layer 73. FIG. 15o illustrates a separate confinement blue laser including a p-type layer of zinc sulfur selenide 75, a zinc cadmium selenide quantum well 76 and an n-type zinc sulfur selenide layer 77. Finally, FIG. 15p illustrates a separate confinement MQW blue laser including a p-type layer of zinc sulfur selenide 81, an MQW of zinc sulfur selenide and zinc cadmium selenide 82, and an n-type layer of zinc sulfur selenide 83.

Each of the structures of FIGS. 15a-15p includes the ohmic contact shown in FIG. 12, including a layer of mercury selenide 18 and a graded zinc mercury selenide layer or zinc telluride selenide layer 19. The ohmic contact of FIG. 1, which includes a mercury selenide layer 18 and is free of a zinc mercury selenide layer 19, may also be used. It will be understood that other configurations of the optical structure 11 may also be used.

It will also be understood that in any of the heterojunctions previously described, band discontinuities can be reduced or eliminated by modulation doping. Modulation doping is a technique which is well known to those having skill in the art, and is described for Group III-V semiconductors in an article by Shupert et al. entitled *Elimination of Heterojunction Band Discontinuities By Modulation Doping*, Applied Physics Letters, Vol. 16, No. 4, January 1992, pp. 466-468.

Techniques for fabricating the ohmic contacts of the present invention will now be described. At present, molecular beam epitaxy (MBE) is the preferred deposition technique for preparing integrated heterostructure

devices of Group II-VI compound semiconductors for blue to green light emitter applications. This is because p-type doping is possible using nitrogen excited in a remote-plasma-enhanced MBE source, such as the model MPD21 marketed by Oxford Applied Research, Oxfordshire, England. Organometallic vapor deposition (OMCVD) is a second potential deposition technique for growing integrated heterostructure devices, if p-type doping is developed. At present, p-type doping of zinc selenide and related alloys by OMCVD has not been demonstrated, to the best of the inventor's knowledge.

The integrated heterostructure devices of the present invention may be fabricated using a two chamber MBE deposition system. In the integrated heterostructure including the zinc mercury selenide layer 19, a first deposition chamber may be used exclusively for the deposition of wide bandgap Group II-VI semiconductor layers including zinc selenide, zinc cadmium selenide and zinc sulfur selenide, to grow the optical portion 11 of the integrated heterostructure device according to any of the structures described above or any other Group II-VI optical structure. The sample is then transferred to a second chamber where mercury selenide, or zinc mercury selenide and mercury selenide, is heteroepitaxially formed on the p-type zinc selenide. A second chamber is typically required because of the special requirements for depositing mercury based materials which are necessitated by the extremely high vapor pressure of mercury (about 3 mTorr at room temperature). Accordingly, as is well known to those having skill in the art, special MBE sources, cryoshrouding and other special techniques may need to be employed.

A detailed process for forming a separate confinement green laser having an ohmic contact using zinc mercury selenide according to the present invention will now be described. The laser structure is shown in FIG. 17 and includes an optical heterostructure 11 comprising a zinc cadmium selenide quantum well 87 between p- and n-type zinc selenide layers 86 and 88, respectively, which are placed between p-and-n zinc sulfur selenide layers 85 and 89, respectively. The optical heterostructure 11 is formed on substrate 15 and includes a top layer 17 of p-type zinc selenide. The ohmic contact heterostructure comprises a layer of graded zinc mercury selenide 19 and a layer of mercury selenide 18 between metal electrode 13 and p-type zinc selenide layer 17.

Conventional substrate preparation processes are used to form an n+ gallium arsenide or zinc selenide substrate 15. Epitaxial growth of the p-on-n heterostructure is initiated at a substrate temperature of 220°-260° C. Chlorine, in the form of the solid zinc chloride, is presently the preferred n-type dopant for the n-type zinc sulfur selenide layer 89 and the n-type zinc selenide optical confinement layer 88. Doping levels for layers 88 and 89 should be about 10^{18} cm⁻³. The zinc cadmium selenide quantum well 87 is then deposited, followed by the p-type zinc selenide layer 86 and the p-type zinc sulfur selenide layer 85.

Two techniques may be used to effectively form layers 17, 18 and 19 on layer 85. A first technique transfers the already completed structure into a second chamber under ultrahigh vacuum, using commercially available ultrahigh vacuum interlocking systems or a portable ultrahigh vacuum wafer transfer device. Alternatively, a second technique avoids the need to transfer

the optical heterostructure to a second deposition chamber under ultrahigh vacuum by forming a thin overcoat layer, for example selenium, on the structure.

FIGS. 18a and 18b illustrate the use of the selenium overcoat layer. Referring to FIG. 18a, a thin (e.g. about 0.1 μm) layer of selenium 91 may be formed in the first chamber 92 after the deposition sequence described above. The selenium layer deposition may take place at room temperature. Then, the sample can be removed from the first chamber 92 and inserted into a second chamber 93 for mercury based heterostructure growth. In the second chamber 93, the selenium layer 91 may be evaporated by heating the substrate at 300° C. for several minutes just prior to mercury based film growth to obtain the structure of FIG. 18b.

Once the sample in chamber 93 is ready for deposition, a thin (approximately 200 Å) p-type layer of zinc selenide 17 is deposited followed by a graded p-type zinc mercury selenide region 19, and a thin (approximately 200 Å) layer of mercury selenide 18. The exact thickness of the layers is not critical. Preferably, at least part or all of the graded zinc mercury selenide layer is doped p-type to effectively eliminate band discontinuities. At present, nitrogen from a remote plasma source is the preferred p-type dopant. During deposition of the $\text{Zn}_x\text{Hg}_{1-x}\text{Se}$ graded layer, in which the x value is graded from x=1 to x=0, the substrate temperature is preferably reduced from about 220°–260° C. initially to about 100° C. in order to effectively incorporate the mercury into the graded zinc mercury selenide layer 19. Zinc and selenium fluxes must also be adjusted for proper growth of the zinc mercury selenide layer. If this adjustment is not done, practically all of the mercury reevaporates and grading of the layer does not occur. The final mercury selenide layer 18 is then deposited at about 100° C.

FIGS. 19A and 19B illustrate a two chamber process using a selenium overcoat layer to form an integrated heterostructure device including a zinc telluride selenide layer 19. Referring to FIG. 19A, the optical heterostructure 11 and p-type zinc selenide layer 17 are fabricated in first chamber 92 as was already described in FIG. 18A. Then, zinc telluride selenide layer 19 is grown in first chamber 92 by continuing growth at about 250° C. A graded layer of zinc telluride selenide that is doped p-type with nitrogen from the plasma source is grown by decreasing the temperature of the selenium MBE source oven under computer control while increasing the source temperature of the tellurium MBE source oven. In this way, a p-type graded layer which initially is composed of zinc selenide and finally is composed of zinc telluride is prepared. A preferred thickness of between about 500–1500 Å is grown. The final fluxes may be maintained for an additional short time period to form an optional thin layer (about 100 Å) of p-type zinc telluride. Additional growth of zinc telluride ensures a pure zinc telluride interface with the mercury selenide layer formed thereon.

Following deposition of the zinc tellurium selenide layer 19, a capping formed as was already described in connection with FIG. 18A. The selenium capped structure is then transferred to the second MBE chamber 93 as shown in FIG. 19B. As was already described in connection with FIG. 18B, in the second chamber 93, the selenium layer 91 is desorbed and a thin layer of mercury selenide 18 (FIG. 17) is deposited at about 100° C. in the mercury based MBE chamber.

The zinc telluride selenide layer 19 of the present invention can be grown in the first MBE chamber 92 using the same growth temperature (about 250° C.) as the optical heterostructure 11 of the integrated heterostructure device. Moreover, the graded layer can be doped p-type using nitrogen from the same doping source that is used to prepare the p-type layers of the optical portion 11 of the integrated heterostructure device. Accordingly, the fabrication process for the graded layer of zinc telluride selenide is simpler than the graded zinc mercury selenide layer described in FIGS. 18A and 18B.

FIGS. 20 and 21 graphically illustrate the improved performance obtained using the zinc telluride selenide layer 19 according to the present invention. Two identical structures, differing only in the presence of the zinc telluride selenide layer were grown to compare the performance of the integrated heterostructure with and without the zinc telluride selenide layer. In particular, the optical heterostructure 11 of FIG. 16E was grown in the first MBE system 92 (FIG. 18A or 19A) and capped with a thin layer of selenium. The structure was then transferred to the second MBE system 93 (FIG. 18B or 19B) where the selenium was desorbed and the thin mercury selenide layer was grown at about 100° C. Then, half of the sample was processed into light emitting diodes, while the other half was reinserted into first chamber 92 (FIG. 18A or 19A). The mercury selenide layer was desorbed and a linear graded, all p-type layer of zinc telluride selenide was grown. The sample was again capped with selenium and reinserted into the second MBE chamber 93 (FIG. 19B) where the selenium layer was desorbed and the thin mercury selenide layer 18 was grown by MBE. Accordingly, a sample with identical optical heterostructures was prepared, with and without the zinc telluride selenide layer 19.

FIG. 20 illustrates the properties of the LED structure with the zinc tellurium selenide layer 19 absent. As shown, the diode turns on, or begins conducting appreciable current, at about 2.8 volts and generates 10 milliamperes at about 4.4 volts. The forward bias characteristics are "soft", because of the 0.6 electron volt barrier between mercury selenide and zinc selenide.

FIG. 21 graphically illustrates the properties of the identical LED structure including the layer of zinc telluride selenide. As shown, the turn-on voltage is reduced to about 1.9 electron volts and the LED generates 10 milliamperes at about 3.2 electron volts. In addition, the forward bias characteristics of the diode correspond to a series resistance of only about 75 Ω . This is reflected in the much sharper forward bias characteristics compared with FIG. 20.

Hall effect measurements using a mercury selenide ohmic contact yield a room temperature mobility μ_p of 19 $\text{cm}^2/\text{V-s}$ and a room temperature hole concentration of $5 \times 10^{18} \text{ cm}^{-3}$. Based on a review of the literature, it is estimated that the valance band of zinc telluride is within 0.2 eV \pm 0.4 eV of that of mercury selenide. See the publications by R. H. Miles et al. entitled *Superlattices of II-VI Semiconductors*, Journal of Crystal Growth, Vol. 85, pp. 188–193 (1987), Kobayashi et al. entitled *Growth and Characterization of ZnSe-ZnTe Strained-Layer Superlattices*, Journal of Crystal Growth, Vol. 81, pp. 495–500 (1987), and Y. Rajakarunanayake et al. entitled *Band Offset of the ZnSe-ZnTe Superlattices: A Fit to Photoluminescence Data by k_p Theory*, Journal of Vacuum Science Technology, Vol. B6, No. 4, July/August 1988, pp. 1354–1359. By optimizing the

p-type doping of the zinc telluride selenide layer and its grading, shape and thickness, it should be possible to further reduce the series resistance to less than 10 Ω .

Similar procedures may be used to fabricate a variety of other integrated heterostructures for blue laser, blue LED, green laser and green LED applications, and other applications. The color output of a particular device is determined by the cadmium content of the zinc cadmium selenide layers in the active regions of the structure. The degree of optical confinement is determined by the sulfur content in the zinc sulfur selenide cladding layers. The graded structure of p-type doped zinc mercury selenide or zinc telluride selenide further reduces the valance band offset between mercury selenide and zinc selenide and thus further reduces the series resistance of the ohmic contact. The series resistance and turn-on voltage of the optical device is thereby minimized.

It is also possible to grow p-on-n integrated heterostructure devices on insulating substrates. This might be desirable, for example, because of the limited availability of n-type ZnSe substrates at present. If an insulating substrate is employed, the multilayered growth sequence remains unchanged from that described above. However, the finished wafers are processed differently so that an ohmic contact can be made to the initial n-type epitaxial layer of the structure. This can be done by employing standard photolithography/etching techniques to define mesas and etch down to the n-type layer as shown in FIG. 16. A 1% bromine in methanol solution is a suitable etchant for the Hg-based layers. A solution of 1 gm potassium dichromate ($K_2Cr_2O_7$), 10 ml sulfuric acid (H_2SO_4), and 20 ml of deionized water is suitable for etching ZnSe and related alloys. Both solutions are compatible with available photoresists. Following this etching step, ohmic contact to the n-type layer can then be achieved by photolithographically defining and opening via regions to the n-type layer and depositing an appropriate metal such as indium, or indium/gold. Standard liftoff techniques can then be used to remove the deposited metal from unwanted areas of the structure.

Referring now to FIG. 22, a high efficiency blue/green light emitting diode according to the present invention is illustrated. Diode 10 includes the quaternary alloy zinc sulfur telluride selenide ($ZnS_xTe_ySe_z$, where $x+y+z=1$) between layers of zinc sulfur selenide (ZnSSe). In particular, as shown in FIG. 22, a substrate 15 of n-type gallium arsenide includes a layer 16 of n-type zinc sulfur selenide thereon. Preferably, layer 16 is $ZnS_{0.07}Se_{0.93}$, which is lattice matched to gallium arsenide. Region 31 of $ZnS_xTe_ySe_z$ is formed on region 16 and p-type zinc sulfur selenide region 17 is formed thereon. An ohmic contact such as a layer of zinc mercury selenide or zinc telluride selenide 19 and a layer of mercury selenide is included. Metal contact layers 13 and 14 are also included as was described above. Cladding layers 16 and 17 are preferably doped at 1×10^{18} dopants cm^{-2} and layer 31 is preferably about 1000 \AA thick for an LED and about 100–200 \AA thick for a laser. It will also be understood by those having skill in the art that a multiple quantum well of zinc sulfur telluride selenide and zinc sulfur selenide may be provided between cladding layers 16 and 17.

FIG. 23 illustrates a similar structure which is optimized for formation on n-type zinc selenide substrate 15. Since the substrate 15 is zinc selenide, sulfur is not employed in this structure.

Tellurium is known to form an isoelectronic trap in zinc selenide and zinc sulfur selenide which produces a broad and intense light output in the blue/green spectral region as measured by photoluminescence and electroluminescence experiments. The addition of tellurium to the active region 31 of the optical emitter produces an isoelectronic trap similar to that which occurs when tellurium is added to zinc selenide, which results in intense broadband photoluminescent and electroluminescent output in the green to blue/green spectral region at room temperature, depending on the tellurium content of the alloy 31. FIG. 24 illustrates the spectral output (wavelength versus arbitrary intensity) of an LED fabricated according to FIG. 22. At a temperature of 300° K and an input current of 50 milliamps, the green LED exhibits an absolute efficiency η of 6×10^{-4} and an output power of 85 microwatts. The peak wavelength is 504 nanometers and the dominant wavelength is 503 nanometers. The optical purity is 61%. Optimization of the materials growth parameters, layer thicknesses and device packaging may be expected to give rise to even higher LED efficiencies at room temperature.

Referring now to FIG. 25, an inverted integrated heterostructure device 100 according to the present invention is illustrated. Integrated heterostructure 100 includes an optical heterostructure 11 and an electrical heterostructure 12. Optical heterostructure 11 can be any one of the optical heterostructures 11 previously described, or other well known blue to green optical emission structures or any other Group II-VI device now known or discovered later. As shown in FIG. 25, the optical emission heterostructure 11 includes an active region 101 such as a quantum well, a multiple quantum well, a graded index separate confinement heterostructure, or other well known active region, between layers of n-type zinc selenide 16 and p-type zinc selenide 17. An electrical heterostructure 12 is also formed on p-type zinc selenide layers 17. As already described, the electrical heterostructure includes a layer of zinc mercury selenide or zinc telluride selenide 19 and a layer of mercury selenide 18 on layer 19. Layer 19 is preferably a graded layer as was already described.

Still referring to FIG. 25, a transparent ohmic electrode 102, such as n-type indium oxide or indium tin oxide, is used to make an ohmic contact to the top n-type zinc selenide layer 16. An ohmic electrode 13 contacts mercury selenide layer 18. Ohmic electrode 13 is preferably an optically reflecting metal ohmic electrode such as gold, platinum, aluminum or indium. The structure also preferably includes a substrate 103 which may be electrically conducting as will be described below.

Accordingly, the integrated heterostructure 100 of FIG. 25 is inverted compared to the previous figures, such that the electrical heterostructure 12 is beneath the optical heterostructure 11 and optical emissions occur through n-type zinc selenide layer 16 and transparent ohmic electrode 102. Optical emissions produced from the optical heterostructure 11 to the mercury selenide layer 18 are preferably reflected by ohmic electrode 13 to enhance optical emission efficiency.

Referring now to FIGS. 26A–26E, a method for fabricating the inverted integrated heterostructure of FIG. 25 will now be described. Referring to FIG. 26A, an optical emission heterostructure 11 and an electrical heterostructure 12 are epitaxially formed on a substrate 15 such as a zinc selenide or gallium arsenide substrate,

as already described extensively with regard to the previous figures.

Then, referring to FIG. 26B, mercury selenide layer 18 is metallized with a first ohmic metal electrode 13, preferably a reflecting ohmic metal electrode such as gold, platinum, aluminum or indium. A second substrate 103 is provided, and includes a second and a third ohmic metal electrodes 104 and 105, respectively, on opposite faces thereof. As will be described below, substrate 103 is preferably a conducting substrate and may be a metal or semiconductor substrate, or combinations thereof, depending on the particular application. A bonding layer, such as a conducting epoxy or solder is also formed between the first and second ohmic metal electrodes 13 and 104, respectively. It will be understood that bonding layer 106 may be applied to either or both of layers 13 and 104.

Referring now to FIG. 26c, the first and second ohmic metal electrodes 13 and 104 are bonded together via bonding layer 106 to form a single structure. Then, referring to FIG. 26C, the original substrate 15 is removed, for example, by mechanical lapping and chemical etching. In particular, if the original substrate is gallium arsenide, a stop-etch solution of $\text{NH}_4\text{OH}:\text{H}_2\text{O}_2$, of approximately 1:10 by volume, may be used. The ammonium hydroxide (NH_4OH) is a standard solution and the hydrogen peroxide (H_2O_2) is a 30% solution. This solution readily removes gallium arsenide but does not etch zinc selenide or related Group II-VI compounds. Alternatively, if the original substrate is zinc selenide, then mechanical lapping followed by chemical etching in a 1% bromine in methanol solution, followed by reactive ion etching using boron trichloride gas, may be used. Other appropriate etching techniques will be known by those having skill in the art for other substrates.

Finally, referring to FIG. 26E, a transparent ohmic electrode 102 may be formed on n-type zinc selenide layer 16. Appropriate external contacts may be added to layers 102 and 105, and antireflective coatings and other passivating coatings may be added to encapsulate the device, using materials and techniques well known to those having skill in the art.

As described in FIG. 26D, the original substrate 15 which was used to epitaxially form the integrated heterostructure, is removed. When a gallium arsenide substrate is used to grow a Group II-VI integrated heterostructure, the zinc selenide/gallium arsenide interface is usually found to contain a large density of misfits and other dislocations which extend into the epitaxial layer for one micron or more. The method of FIGS. 26A-26E allows the removal of this defective interfacial layer after removal of the original substrate 15 using suitable etching procedures. For example, reactive ion etching using boron trichloride as the etching gas can be used to etch the surface of the n-type zinc selenide to remove such a defective surface layer. Under appropriate soft-etching conditions, the defective surface layer can be removed without introducing significant damage to the zinc selenide based structure. Thus, the inverted integrated heterostructure eliminates heteroepitaxy induced defects associated with lattice mismatch, which is one of the major causes for dark line and other defects that limit the lifetime of blue/green light emitters based on Group II-VI materials.

Referring now to FIGS. 27-29, three examples of inverted integrated heterostructure devices according to the invention will be described. A light emitting

diode is described in FIG. 27, a large area light emitting diode is described in FIG. 28 and a laser diode is described in FIG. 29. These embodiments are provided in order to describe epitaxial layer combinations which are presently preferred for each application. However, it will be understood by those having skill in the art that many other embodiments of integrated heterostructure devices may be produced.

Referring now to FIG. 27, an example of a light emitting diode 120 is shown. The light emitting diode 120 corresponds to the integrated heterostructure described in FIG. 26E with the addition of an antireflective coating 111, a metal contact 112 to the transparent ohmic electrode 102, and electrical biasing sources 113 and 114 for powering the devices. The antireflective coating 111 may be a single layer of a low refractive index material such as magnesium fluoride (refractive index about 1.35), a two layer high-low stack of ZnS (refractive index about 2.6) and magnesium fluoride (refractive index about 1.35), or other suitable stacks of antireflective materials. Alternatively, the LED 120 can be packaged as a lamp, in which case the epoxy-based material of the lamp serves as both a focusing lens and an antireflecting coating having index of refraction of 1.5-1.6.

As already described, the inversion process of the present invention uses a highly-conductive bonding layer 106 to bond the original integrated heterostructure to the conducting substrate 103 as shown. The conducting substrate 103 is pre-metallized and annealed prior to bonding to, provide broad area ohmic contacts 104 and 105 to both of its surfaces. The conducting substrate 103 can be metal such as copper (for heat-sinking purposes) or a heavily doped semiconductor such as gallium arsenide or silicon, or combinations thereof, or other suitable substrates, depending on the particular application. The LED structure of FIG. 27 is electrically biased as shown to provide the forward-bias condition required for light emission from the device.

The inverted LED structure 120 of FIG. 27 has several important features: First, the device has excellent heat-sinking characteristics since the electrical heterostructure 12 which may be expected to generate the most heat, is in direct contact with the highly-conductive substrate 103. Moreover, the LED structure of the present invention is designed so that most of the light generated within the active region 101 becomes externally-emitted light, thereby significantly increasing the external efficiency of the LED. This is so because the top electrode 102 is semitransparent. In addition, the bottom electrode includes a very thin semi-transparent layer of HgSe 18 (about 100 Å) followed by a metal 13. Thus, the bottom electrode serves as a highly reflecting mirror that reflects most of the light generated within the active region of the device upward and out through the top transparent electrode 102, thereby contributing additional significant radiation to the external light emission of the device.

The external efficiency (power efficiency) of an LED is defined as the total light output power divided by the electrical input power. Conventional MESA-type LEDs based on III-V materials equipped with metal electrodes that are presentably available commercially generally display external efficiencies of 1-2% (red LEDs), 0.1% (green LEDs), and less than 0.1% (blue silicon carbide LEDs). External efficiencies approaching 0.1% at room temperature have been achieved for blue/green LEDs fabricated as an integrated heterostructure of Group II-VI semiconductor materials in-

cluding the epitaxial ohmic contact. It is estimated, however, that only 1-2% of the light generated by the II-VI light emitter actually leaves the device as output radiation. This is so because the index of refraction of GaAs (about 3.6) is larger than that of ZnSe (about 2.8). As a consequence, there is no total internal reflection at the interface of the ZnSe layer 16 and the GaAs substrate 15, and nearly all of the light generated within the active region of the II-VI integrated heterostructure device is absorbed by the GaAs substrate 15. The inverted integrated heterostructure of the present invention greatly reduces this loss mechanism by removing the absorbing GaAs substrate 15 and replacing it with a semitransparent top electrode 102. Additionally, the reflecting mirror surface 13 at the base of the p-type cladding layer 17 substantially increases the external light output since most of the light that strikes this interface is reflected upwards and out of the LED as useful light emission.

Theoretical calculations indicate that the inverted structure of the present invention is capable of increasing the external efficiency of an LED structure by as much as a factor of twenty or more under ideal conditions compared with blue/green LEDs fabricated as MESAs on GaAs substrates with top metal electrodes.

There are three major loss mechanisms that affect the light output from an LED: The first mechanism is absorption loss within the semiconductor medium. By using a double-heterostructure in which the active region emits light at an energy less than the cladding layers that surround it, absorptive loss is minimal. For the LED structure of FIG. 27, the total loss due to absorption (absorption efficiency) within the medium and reflecting base is estimated to be $\eta_a \cong 0.8$.

The second principal LED loss mechanism is due to "Fresnel loss" which takes into account the different index of refraction of the semiconductor medium n_1 , the antireflective coating n_2 , and the outside air $n_3=1$ which affects the transmission of light from the active region of the device into the ambient air. The Fresnel loss efficiency factor η_F associated with an interface between materials of indices n_1 and n_2 is given by:

$$\eta_F = 4/[2 + (n_1/n_2) + (n_2/n_1)] \quad (3)$$

See for example, *Optoelectronics/Fiber-Optics Applications Manual*, second edition, prepared by the staff of the Hewlett-Packard Optoelectronics Division, published by McGraw-Hill Book Company (McGraw-Hill book number 0-07-028606-X), New York (1981), Chapters 1 and 2. For the LED structure of FIG. 27 with an antireflective coating of index $n_2=1.6$ (which is realizable with certain epoxies used in LED lamp fabrication), the estimated Fresnel loss efficiency is $\eta_F=0.93$ at the semiconductor-epoxy interface, and $\eta_F=0.94$ at the epoxy-air interface. Thus, the total Fresnel loss efficiency for the structure of FIG. 27 as an encapsulated lamp is

$$\eta_F = (0.93) \times (0.94) = 0.88.$$

The third major loss factor is due to critical-angle loss. For the LED structure of FIG. 27 equipped with an epoxy dome lens (standard lamp packaging) the critical-angle efficiency is given by:

$$\eta_c = (n_2/n_1)^2 \quad (4)$$

See for example, *Optoelectronics/Fiber-Optics Applications Manual*, second edition, prepared by the staff of the Hewlett-Packard Optoelectronics Division, published by McGraw-Hill Book Company (McGraw-Hill book number 0-07-028606-X), New York (1981), Chapters 1 and 2. Thus, for the LED structure of FIG. 27 equipped with an epoxy dome lens, the critical angle efficiency is

$$\eta_c = (1.6/2.8)^2 = 0.32$$

The estimated total external efficiency of the LED device of the present invention is thus given by:

$$\eta_{total} = (\eta_a) \times (\eta_F) \times (\eta_c) = (0.8) \times (0.8) \times (0.32) = 0.22. \quad (5)$$

Thus, the present invention, packaged in a domed lamp configuration, can produce blue and green LEDs with external efficiencies of up to 22%. The preceding analysis assumes an internal conversion efficiency of unity (one photon per each electron-hole pair recombination in an active region of the device). However, even if the internal efficiency of the semiconductor medium is only 5%, LEDs with external efficiencies of greater than 1% are possible.

Accordingly, the present invention obtains high-brightness blue and green LEDs, which are needed for many different applications. High-brightness red LEDs, composed of III-V materials (GaAsP junctions on GaP substrates) are already available. The present invention provides the missing elements for the construction of high-brightness full-color displays based on mixing the three primary colors of red, green, and blue.

Referring now to FIG. 28, the structure described in FIG. 27 is also suitable for the fabrication of large-area light emitting diodes (LEDs). Large area LEDs are desirable in applications which require high-brightness light outputs, and in cases where patterning of the light emitter is required, such as seven-segment integer displays, geometric shapes, or company logos. An example of a large area inverted-integrated heterostructure LED device is shown in FIG. 28. The structure 130 is fabricated as described above. Standard photolithographic techniques are used to define the surface geometry of the large-area device. In addition, the device is equipped with a metal grid electrode 112a-112n to insure good electrical contact to the top transparent conducting electrode.

For a large area device, adequate heat sinking is necessary, since the device may require several watts of input power under operating conditions. The large-area inverted-IHD LED structure shown in FIG. 28 provides excellent heat sinking of the device, since the conducting substrate 103 can be a copper-block heat sink that is fan-cooled or water-cooled if necessary.

Referring now to FIG. 29, an embodiment of a laser diode according to the invention is described. Laser diode 140 is fabricated as was already described with respect to FIG. 27, with the following major differences:

(1) The original structure of FIG. 26A is bonded to a lattice-matched second substrate 103 of the same crystallographic orientation. Either GaAs or ZnSe are the preferred substrate choices.

(2) After the etching and metallization steps FIG. 26D are completed using standard photolithographic procedures, the base and side walls of the structure are passivated with a surface passivant layer 115 (FIG. 29).

Zinc sulfide, silicon dioxide, or silicon nitride are presently passivant/insulators of choice.

(3) The wafer is then sawed into strips ~1 mm wide, and each strip is cleaved into several laser cavities. The cleaving operation requires that a lattice-matched and oriented substrate 103 be used. For (100)-oriented epitaxial wafers on an appropriate lattice-matched and oriented substrate, the cleaved surfaces of the laser device should expose a set of {110} cleavage planes. For (111)-oriented epitaxial wafers, the cleaved faces must also correspond to a set of parallel {110} cleavage planes. Cavity lengths from 250–1000 μm are preferred for laser diode applications.

Operation of the laser diode 140 is explained because the current through the entire circuit shown in FIG. 29 is a constant at every "equipotential" location in the circuit at all times under dc-bias and many pulsed-bias applications. As a consequence, the current density will be higher in small cross-sectional area regions of the device structure, and lower in large cross-sectional area regions, as illustrated by the arrows in region 17. Specifically, if the cross-sectional area of the p-type region 17 near the HgSe contact layer 18 is A_c and the cross-sectional area of the active region of the device 101 is A_d , then the current densities J_c and J_d are related by the conservation of current I requirement:

$$I_d = I_c \quad (6)$$

or

$$J_d A_d = J_c A_c \quad (7)$$

Thus

$$J_d = (A_c/A_d) J_c \quad (8)$$

Equation (6) shows that large current densities J_d at the active region of the device are possible when only moderate current densities J_c are applied to the p-type contact region 17, provided that A_c/A_d is large. As an example, a laser diode having an active region 10 μm wide and 1 mm long (typical of blue/green laser diodes demonstrated to date) with a room temperature threshold current density requirement of 400–800 A/cm^2 at the active region of the device, would only require a current density of about 0.8 A/cm^2 at the p-type contact region, as given by Equation (8), if the cross-sectional area of the contact region is 10^{-2}cm^2 (1 mm \times 1 mm contact area base) and the p-type zinc selenide layer 17 is highly conducting. This implies that the turn-on voltage for the laser structure of FIG. 29 would be less than 4 V, assuming that the p-type cladding layer above the broad-area p-type contact is, in fact, highly conducting.

The p-type cladding layer conductivity is presently limited by present-day p-type doping technology, to about 1×10^{18} holes per cm^3 at room temperature. Thus, there will be some lateral voltage drop associated with the structure of FIG. 29, and this will limit the actual current spreading. Notwithstanding this present day limitation, the laser diode of FIG. 29 provides for reduced operating voltages, well below the 20–40 V required for present day blue/green II-VI laser diodes equipped with metal contacts. This decreased operating voltage will be accompanied by significantly-decreased heating effects, since the input power that goes into heating the structure is directly proportional to V. In addition, lower operating voltages imply higher device

efficiencies, all other factors being equal. Improved laser diodes are thereby provided.

In the drawings and specification, there have been disclosed typical preferred embodiments of the invention and, although specific terms are employed, they are used in a generic and descriptive sense only and not for purposes of limitation, the scope of the invention being set forth in the following claims.

That which is claimed:

1. A semiconductor device formed of Group II-VI compound semiconductor materials comprising:

an optical emission heterostructure formed of group II-VI compound semiconductor materials, having first and second opposing faces and including a layer of p-type zinc selenide (ZnSe) or an alloy thereof at said first face thereof;

a zinc mercury selenide ($\text{Zn}_x\text{Hg}_{1-x}\text{Se}$) layer or a zinc telluride selenide ($\text{ZnTe}_x\text{Se}_{1-x}$) layer on said layer of p-type ZnSe or an alloy thereof, where $0 < x < 1$;

a mercury selenide (HgSe) layer on said $\text{Zn}_x\text{Hg}_{1-x}\text{Se}$ layer or said $\text{ZnTe}_x\text{Se}_{1-x}$ layer, opposite said optical emission heterostructure;

an ohmic electrode on said HgSe layer, opposite said $\text{Zn}_x\text{Hg}_{1-x}\text{Se}$ layer or said $\text{ZnTe}_x\text{Se}_{1-x}$ layer; and

a transparent ohmic electrode on said second face of said optical emission heterostructure, for allowing optical emissions from said optical emission heterostructure to pass therethrough.

2. The semiconductor device of claim 1 wherein said ohmic electrode is an optically reflecting ohmic electrode, for reflecting optical emissions from said optical emission heterostructure back into said optical emission heterostructure.

3. The semiconductor device of claim 1 further comprising a substrate on said ohmic electrode, opposite said HgSe layer.

4. The semiconductor device of claim 3 wherein said ohmic electrode is a first ohmic metal electrode and wherein said substrate is an electrically conducting substrate.

5. The semiconductor device of claim 4 wherein said electrically conducting substrate includes a second ohmic metal electrode thereon, said semiconductor device further comprising an electrically conducting bonding layer between said first ohmic metal electrode and said second ohmic metal electrode.

6. The semiconductor device of claim 3 wherein said substrate is a metal substrate which is sufficiently thermally conductive to dissipate heat generated by said semiconductor device in operation.

7. The semiconductor device of claim 3 wherein said substrate is a heavily doped n-type monocrystalline semiconductor substrate.

8. The semiconductor device of claim 7 wherein said substrate is a heavily doped n-type gallium arsenide substrate.

9. The semiconductor device of claim 1 wherein x is constant in said $\text{Zn}_x\text{Hg}_{1-x}\text{Se}$ layer or said $\text{Zn}_x\text{Te}_x\text{Se}_{1-x}$ layer to provide a step graded layer.

10. The semiconductor device of claim 1 wherein x decreases across said $\text{Zn}_x\text{Hg}_{1-x}\text{Se}$ layer or said $\text{Zn}_x\text{Te}_x\text{Se}_{1-x}$ layer from said p-type ZnSe layer or an alloy thereof to said HgSe layer to provide a graded layer.

11. The semiconductor device of claim 10 wherein at least a portion of said $\text{Zn}_x\text{Hg}_{1-x}\text{Se}$ layer or said $\text{Zn}_x\text{Te}_x\text{Se}_{1-x}$ layer is p-type.

12. The semiconductor device of claim 1 further comprising a metal grid electrode on said transparent ohmic

electrode opposite said optical emission heterostructure, for producing large area optical emissions through said transparent ohmic electrode.

13. A semiconductor laser formed of Group II-VI compound semiconductor materials comprising:

a laser heterostructure formed of group II-VI compound semiconductor materials, having a predetermined crystallographic orientation and having first and second opposing faces and including a layer of p-type zinc selenide (ZnSe) or an alloy thereof at said first face thereof;

a zinc mercury selenide ($Zn_xHg_{1-x}Se$) layer or a zinc telluride selenide ($ZnTe_xSe_{1-x}$) layer on said layer of p-type ZnSe or an alloy thereof, where $0 < x < 1$;

a mercury selenide (HgSe) layer on said $Zn_xHg_{1-x}Se$ layer or said $ZnTe_xSe_{1-x}$ layer, opposite said laser heterostructure;

an ohmic metal electrode on said HgSe layer, opposite said $Zn_xHg_{1-x}Se$ layer or said $ZnTe_xSe_{1-x}$ layer; and

a semiconductor substrate having said predetermined crystallographic orientation, on said ohmic metal electrode opposite said HgSe layer.

14. The semiconductor laser of claim 13 wherein said laser heterostructure and said semiconductor substrate are lattice matched to one another.

15. The semiconductor laser of claim 14 wherein said semiconductor substrate is selected from the group consisting of heavily doped n-type gallium arsenide and heavily doped n-type zinc selenide.

16. The semiconductor laser of claim 13 wherein said semiconductor substrate is an electrically conducting semiconductor substrate and includes a second ohmic metal electrode thereon, said semiconductor laser further comprising an electrically conducting bonding layer between said first ohmic metal electrode and said second ohmic metal electrode.

17. The semiconductor laser of claim 13 wherein said active region has a first cross-sectional area and wherein said layer of p-type zinc selenide or an alloy thereof has a second cross-sectional area which is greater than said first cross-sectional area.

18. A method of forming a Group II-VI compound semiconductor device comprising the steps of:

forming on a first substrate, an optical emission heterostructure of Group II-VI compound semiconductor materials, including a layer of p-type zinc selenide (ZnSe) or an alloy thereof opposite said first substrate, a zinc mercury selenide ($Zn_xHg_{1-x}Se$) layer or a zinc telluride selenide ($ZnTe_xSe_{1-x}$) layer on said layer of p-type ZnSe or an alloy

thereof, where $0 < x < 1$, and a mercury selenide (HgSe) layer on said $Zn_xHg_{1-x}Se$ layer or said $ZnTe_xSe_{1-x}$ layer, opposite said optical emission heterostructure;

bonding said HgSe layer to a second substrate; and removing said first substrate.

19. The method of claim 18 wherein said bonding step comprises the steps of:

forming a first ohmic metal electrode on said HgSe layer, opposite said optical emission heterostructure;

forming a second ohmic metal electrode on said second substrate; and

bonding said first and said second ohmic metal electrodes to one another.

20. The method of claim 19 wherein said first and second ohmic electrode bonding step comprises the step of bonding said first and second ohmic metal electrodes to one another with an electrically conductive bonding layer.

21. The method of claim 19 wherein said first and second ohmic electrode bonding step comprises the step of soldering said first and second ohmic metal electrodes to one another.

22. The method of claim 18 wherein said removing step is followed by the step of forming a transparent ohmic electrode on said optical emission heterostructure, opposite said layer of p-type zinc selenide or an alloy thereof.

23. The method of claim 19 wherein said second substrate is an electrically conductive substrate, said method further comprising the step of forming a third ohmic metal electrode on said second substrate, opposite said second metal electrode.

24. The method of claim 18 wherein said optical emission heterostructure forming step comprises the step of epitaxially forming said optical emission heterostructure on said first substrate.

25. The method of claim 18 wherein said second substrate is a second semiconductor substrate, wherein said optical emission heterostructure has a predetermined crystallographic orientation, and wherein said bonding step comprises the step of bonding said HgSe layer to said second semiconductor substrate in said predetermined crystallographic orientation.

26. The method of claim 25 wherein said bonding step is followed by the step of cleaving said optical emission heterostructure and said second semiconductor substrate, to produce a plurality of semiconductor lasers.

* * * * *

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 5,351,255
DATED : September 27, 1994
INVENTOR(S) : Jan F. Schetzina

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

—(e.g.— Column 11, line 52, before "10¹⁸" please insert
Column 12, line 47, please delete "521" and
substitute --Å-- therefor.
Column 12, line 63, after "ZnCdSe" (first
occurrence), please insert --33,--.
Column 12, line 64, after "ZnCdSe" please
insert --35.--.

Signed and Sealed this
Nineteenth Day of September, 1995

Attest:



BRUCE LEHMAN

Attesting Officer

Commissioner of Patents and Trademarks